

## FEATURES

### ARM®720T Processor

- ARM7TDMI CPU Operating at Speeds of 74 and 90 MHz
- 8 kBytes of Four-way Set-associative Cache
- MMU with 64-entry TLB
- Thumb™ Code Support Enabled

### Ultra low power

- 90 mW at 74 MHz Typical
- 108 mW at 90 MHz Typical
- <.03 mW in the Standby State

### Advanced Audio Decoder/decompression Capability

- Supports bit streams with adaptive bit rates.
- Allows for support of multiple audio decompression algorithms (MP3, WMA, AAC, Audible, etc.).



**High-performance,  
Low-power, System-on-chip  
with SDRAM & Enhanced  
Digital Audio Interface**

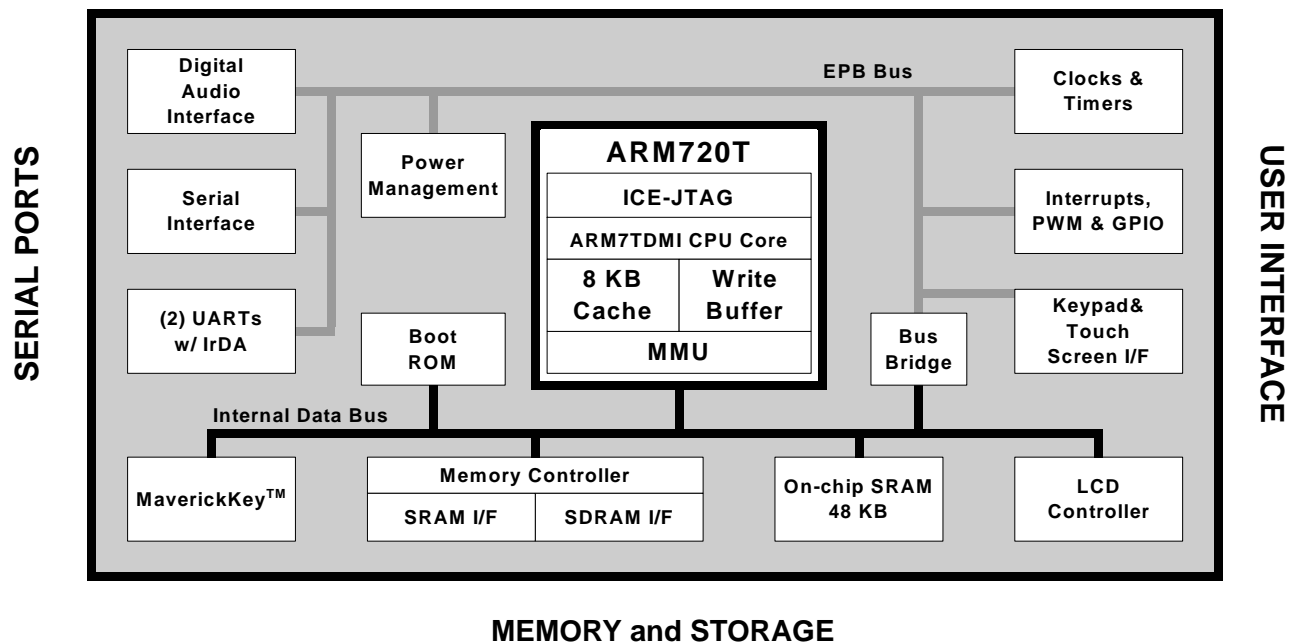
## OVERVIEW

The Cirrus Logic™ EP7312 is designed for ultra-low-power portable and line-powered applications such as portable consumer entertainment devices, home and car audio juke box systems, and general purpose industrial control applications, or any device that features the added capability of digital audio compression & decompression. The core-logic functionality of the device is built around an ARM720T processor with 8 kBytes of four-way set-associative unified cache and a write buffer. Incorporated into the ARM720T is an enhanced memory management unit (MMU) which allows for support of sophisticated operating systems like Microsoft® Windows® CE and Linux®.

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## BLOCK DIAGRAM



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## FEATURES (cont)

48 KBytes of On-chip SRAM

MaverickKey™ IDs

- 32-bit unique ID can be used for DRM-compliant 128-bit random ID.

Available in 74 and 90 MHz clock speeds.

LCD controller

- Interfaces directly to a single-scan panel monochrome STN LCD.
- Interfaces to a single-scan panel color STN LCD with minimal external glue logic.

Full JTAG Boundary Scan and Embedded ICE® Support  
Integrated Peripheral Interfaces

- 32-bit SDRAM Interface, Up to 2 External Banks
- 8/32/16-bit SRAM/FLASH/ROM Interface
- Digital Audio Interface provides glueless interface to low-power DACs, ADCs, and CODECs.
- Two Synchronous Serial Interfaces (SSI1, SSI2)
- CODEC Sound Interface
- 8×8 Keypad Scanner
- 27 General-purpose Input/Output Pins

- Dedicated LED Flasher Pin from the RTC

Internal Peripherals

- Two 16550-compatible UARTs
- IrDA Interface
- Two PWM Interfaces
- Real-time Clock
- Two General-purpose 16-bit Timers
- Interrupt Controller
- Boot ROM

Package

- 208-Pin LQFP
- 256-Ball PBGA

The fully static EP7312 is optimized for low power dissipation and is fabricated using a 0.25 micron CMOS process.

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## OVERVIEW (cont.)

The EP7312 is designed for ultra-low-power operation. Its core operates at only 2.5 V, while its I/O has an operation range of 2.5 V–3.3 V. The device has three basic power states: operating, idle and standby.

MaverickKey unique hardware programmed IDs are a solution to the growing concern over secure web content and commerce. With Internet security playing an important role in the delivery of digital media such as books or music, traditional software methods are quickly becoming unreliable. The MaverickKey unique IDs provide OEMs with a method of utilizing specific hardware IDs such as those assigned for SDMI (Secure Digital Music Initiative) or any other authentication mechanism.

The EP7312 integrates an interface to enable a direct connection to many low cost, low power, high quality audio converters. In particular, high quality ADCs, DACs, or CODECs such as the Cirrus Logic CS53L32A, CS43L42, and CS42L50 are easily added to an EP73xx design via the DAI. Some of these devices feature digital bass and treble boost, digital volume control and compressor-limiter functions.

Simply by adding desired memory and peripherals to the highly integrated EP7312 completes a low-power system solution. All necessary interface logic is integrated on-chip.

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## Description of the EP7312's Components, Functionality, and Interfaces

The following sections describe the EP7312 in more detail.

### Processor Core - ARM720T

The EP7312 incorporates an ARM 32-bit RISC micro controller that controls a wide range of on-chip peripherals. The processor utilizes a three-stage pipeline consisting of fetch, decode and execute stages. Key features include:

- ARM (32-bit) and Thumb (16-bit compressed) instruction sets
- Enhanced MMU for Microsoft Windows CE and other operating systems
- 8 KB of 4-way set-associative cache.
- Translation Look Aside Buffers with 64 Translated Entries

### Power Management

The EP7312 is designed for ultra-low-power operation. Its core operates at only 2.5 V, while its I/O has an operation range of 2.5 V–3.3 V. The device has three basic power states:

- Operating — This state is the full performance state. All the clocks and peripheral logic are enabled.
- Idle — This state is the same as the Operating State, except the CPU clock is halted while waiting for an event such as a key press.
- Standby — This state is equivalent to the computer being switched off (no display), and the main oscillator shut down. An event such as a key press can wake-up the processor.

Table 1 shows the power management pin assignments.

Table 1. Power Management Pin Assignments

Pin Mnemonic	I/O	Pin Description
BATOK	I	Battery ok input
nEXTPWR	I	External power supply sense input
nPWRFL	I	Power fail sense input
nBATCHG	I	Battery changed sense input

### MaverickKey™ Unique ID

MaverickKey unique hardware programmed IDs are a solution to the growing concern over secure web content and commerce. With Internet security playing an important role in the delivery of digital media such as books or music, traditional software methods are quickly becoming unreliable. The MaverickKey unique IDs provide OEMs with a method of utilizing specific hardware IDs such as those assigned for SDMI (Secure Digital Music Initiative) or any other authentication mechanism.

Both a specific 32-bit ID as well as a 128-bit random ID is programmed into the EP7312 through the use of laser probing technology. These IDs can then be used to match secure copyrighted content with the ID of the target device the EP7312 is powering, and then deliver the copyrighted information over a secure connection. In addition, secure transactions can benefit by also matching device IDs to server IDs. MaverickKey IDs provide a level of hardware security required for today's Internet appliances.

### Memory Interfaces

There are two main external memory interfaces. The first one is the ROM/SRAM/FLASH-style interface that has programmable wait-state timings and includes burst-mode capability, with six chip selects decoding six 256 MB sections of addressable space. For maximum flexibility, each bank can be specified to be 8-, 16-, or 32-bits wide. This allows the use of 8-bit-wide boot ROM options to minimize overall system cost. The on-chip boot ROM can be used in product manufacturing to serially download system code into system FLASH memory. To further minimize system memory requirements and cost, the ARM Thumb instruction set is supported, providing for the use of high-speed 32-bit operations in 16-bit op-codes and yielding industry-leading code density. shows the Static Memory Interface pin assignments.

Table 2. Static Memory Interface Pin Assignments

Pin Mnemonic	I/O	Pin Description
nCS[5:0]	O	Chip select out
A[27:0]	O	Address output
D[31:0]	I/O	Data I/O
nMOE/nSDCAS (Note)	O	ROM expansion OP enable
nMWE/nSDWE (Note)	O	ROM expansion write enable
HALFWORD	O	Halfword access select output
WORD	O	Word access select output
WRITE/nSDRAS (Note)	O	Transfer direction

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

The second is the programmable 16- or 32-bit-wide SDRAM interface that allows direct connection of up to two banks of SDRAM, totaling 512 Mb. To assure the lowest possible power consumption, the EP7312 supports self-refresh SDRAMs, which are placed in a low-power state by the device when it enters the low-power Standby State. [Table 3](#) shows the SDRAM Interface pin assignments.

**Table 3. SDRAM Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
SDCLK	O	SDRAM clock output
SDCKE	O	SDRAM clock enable output
nSDCS[1:0]	O	SDRAM chip select out
WRITE/nSDRAS (Note 2)	O	SDRAM RAS signal output
nMOE/nSDCAS (Note 2)	O	SDRAM CAS control signal
nMWE/nSDWE (Note 2)	O	SDRAM write enable control signal
A[27:15]/DRA[0:12] (Note 1)	O	SDRAM address
A[14:13]/DRA[12:14]	O	SDRAM internal bank select
PD[7:6]/SDQM[1:0] (Note 2)	I/O	SDRAM byte lane mask
SDQM[3:2]	O	SDRAM byte lane mask
D[31:0]	I/O	Data I/O

Note: 1. Pins A[27:13] map to DRA[0:14] respectively. (i.e. A[27]/DRA[0], A[26]/DRA[1], etc.) This is to balance the load for large memory systems.  
 2. Pins are multiplexed. See [Table 19 on page 11](#) for more information.

## Digital Audio Capability

The EP7312 uses its powerful 32-bit RISC processing engine to implement audio decompression algorithms in software. The nature of the on-board RISC processor, and the availability of efficient C-compilers and other software development tools, ensures that a wide range of audio decompression algorithms can easily be ported to and run on the EP7312

## Universal Asynchronous Receiver/Transmitters (UARTs)

The EP7312 includes two 16550-type UARTs for RS-232 serial communications, both of which have two 16-byte FIFOs for receiving and transmitting data. The UARTs support bit rates up to 115.2 kbps. An IrDA SIR protocol encoder/decoder can be optionally switched into the RX/TX signals to/from UART 1 to enable these signals to drive an infrared

communication interface directly. [Table 4](#) shows the UART pin assignments.

**Table 4. Universal Asynchronous Receiver/Transmitters Pin Assignments**

Pin Mnemonic	I/O	Pin Description
TXD[1]	O	UART 1 transmit
RXD[1]	I	UART 1 receive
CTS	I	UART 1 clear to send
DCD	I	UART 1 data carrier detect
DSR	I	UART 1 data set ready
TXD[2]	O	UART 2 transmit
RXD[2]	I	UART 2 receive
LEDDRV	O	Infrared LED drive output
PHDIN	I	Photo diode input

## Digital Audio Interface (DAI)

The EP7312 integrates an interface to enable a direct connection to many low cost, low power, high quality audio converters. In particular, the DAI can directly interface with the Crystal CS43L41/42/43 low-power audio DACs and the Crystal CS53L32 low-power ADC. Some of these devices feature digital bass and treble boost, digital volume control and compressor-limiter functions. [Table 5](#) shows the DAI Interface pin assignments.

**Table 5. DAI Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
SCLK	O	Serial bit clock
SDOUT	O	Serial data out
SDIN	I	Serial data in
LRCK	O	Sample clock
MCLKIN	I	Master clock input
MCLKOUT	O	Master clock output

Note: See [Table 18 on page 11](#) for information on pin multiplexes.

## CODEC Interface

The EP7312 includes an interface to telephony-type CODECs for easy integration into voice-over-IP and other voice communications systems. The CODEC interface is multiplexed to the same pins as the DAI and SSI2. [Table 6](#) shows the CODEC Interface Pin Assignments.

**Table 6. CODEC Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
PCMCLK	O	Serial bit clock
PCMOU	O	Serial data out
PCMIN	I	Serial data in
PCMSYNC	O	Frame sync

Note: See [Table 18 on page 11](#) for information on pin multiplexes.

## SSI2 Interface

An additional SPI/Microwire1-compatible interface is available for both master and slave mode communications. The SSI2 unit shares the same pins as the DAI and CODEC interfaces through a multiplexer. The SSI2 Interface has these features:

- Synchronous clock speeds of up to 512 kHz
- Separate 16 entry TX and RX half-word wide FIFOs
- Half empty/full interrupts for FIFOs
- Separate RX and TX frame sync signals for asymmetric traffic

[Table 7](#) shows the SSI2 Interface pin assignments.

**Table 7. SSI2 Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
SSICLK	I/O	Serial bit clock
SSITXDA	O	Serial data out
SSIRXDA	I	Serial data in
SSITXFR	I/O	Transmit frame sync
SSIRXFR	I/O	Receive frame sync

Note: See [Table 18 on page 11](#) for information on pin multiplexes.

## Synchronous Serial Interface

The EP7312 Synchronous Serial Interface has these features:

- ADC (SSI) Interface: Master mode only; SPI and Microwire1-compatible (128 kbps operation)
- Selectable serial clock polarity

[Table 8](#) shows the Synchronous Serial Interface pin assignments.

**Table 8. Serial Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
ADCLK	O	SSI1 ADC serial clock
ADCIN	I	SSI1 ADC serial input
ADCOUT	O	SSI1 ADC serial output
nADCCS	O	SSI1 ADC chip select
SMPCLK	O	SSI1 ADC sample clock

## LCD Controller

A DMA address generator is provided that fetches video display data for the LCD controller from memory. The display frame buffer start address is programmable, allowing the LCD frame buffer to be in SDRAM, internal SRAM or external SRAM. The LCD controller has these features:

- Interfaces directly to a single-scan panel monochrome STN LCD
- Interfaces to a single-scan panel color STN LCD with minimal external glue logic
- Panel width size is programmable from 32 to 1024 pixels in 16-pixel increments
- Video frame buffer size programmable up to 128 KB
- Bits per pixel of 1, 2, or 4 bits

[Table 9](#) shows the LCD Interface pin assignments.

**Table 9. LCD Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
CL1	O	LCD line clock
CL2	O	LCD pixel clock out
DD[3:0]	O	LCD serial display data bus
FRM	O	LCD frame synchronization pulse
M	O	LCD AC bias drive

## 64-Key Keypad Interface

Matrix keyboards and keypads can be easily read by the EP7312. A dedicated 8-bit column driver output generates



strokes for each keyboard column signal. The pins of Port A, when configured as inputs, can be selectively OR'ed together to provide a keyboard interrupt that is capable of waking the system from a STANDBY or IDLE state. The Keypad Interface has these features:

- Column outputs can be individually set high with the remaining bits left at high-impedance
- Column outputs can be driven all-low, all-high, or all-high-impedance
- Keyboard interrupt driven by OR'ing together all Port A bits
- Keyboard interrupt can be used to wake up the system
- 8x8 keyboard matrix usable with no external logic, extra keys can be added with minimal glue logic

Table 10 shows the Keypad Interface Pin Assignments.

**Table 10. Keypad Interface Pin Assignments**

Pin Mnemonic	I/O	Pin Description
COL[7:0]	O	Keyboard scanner column drive

## Interrupt Controller

When unexpected events arise during the execution of a program (i.e., interrupt or memory fault) an exception is usually generated. When these exceptions occur at the same time, a fixed priority system determines the order in which they are handled. The EP7312 interrupt controller has two interrupt types: interrupt request (IRQ) and fast interrupt request (FIQ). The interrupt controller has the ability to control interrupts from 22 different FIQ and IRQ sources. The Interrupt controller has these features:

- Supports 22 interrupts from a variety of sources (such as UARTs, SSI1, and key matrix.)
- Routes interrupt sources to the ARM720T's IRQ or FIQ (Fast IRQ) inputs
- Five dedicated off-chip interrupt lines operate as level sensitive interrupts

Table 11 shows the interrupt controller pin assignments.

**Table 11. Interrupt Controller Pin Assignments**

Pin Mnemonic	I/O	Pin Description
nEINT[2:1]	I	External interrupt
EINT[3]	I	External interrupt
nEXTFIQ	I	External Fast Interrupt input
nMEDCHG/nBROM (Note)	I	Media change interrupt input

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

## Real-Time Clock

The EP7312 contains a 32-bit Real Time Clock (RTC) that can be written to and read from in the same manner as the timer counters. It also contains a 32-bit output match register which can be programmed to generate an interrupt.

- Driven by an external 32.768 kHz crystal oscillator

Table 12 shows the Real-Time Clock pin assignments.

**Table 12. Real-Time Clock Pin Assignments**

Pin Mnemonic	Pin Description
RTCIN	Real-Time Clock Oscillator Input
RTCOU	Real-Time Clock Oscillator Output
VDDRTC	Real-Time Clock Oscillator Power
VSSRTC	Real-Time Clock Oscillator Ground

## PLL and Clocking

The EP7312 processor and peripheral clocks have these features:

- Processor and peripheral clocks operate from a single 3.6864 MHz crystal or external 13 MHz clock
- Programmable clock speeds allow the peripheral bus to run at 18 MHz when the processor is set to 18 MHz and at 36 MHz when the processor is set to 36, 49 or 74 MHz, and at 45 MHz when the processor is set to 90 MHz.

Table 13 shows the PLL and clocking pin assignments.

**Table 13. PLL and Clocking Pin Assignments**

Pin Mnemonic	Pin Description
MOSCIN	Main Oscillator Input
MOSCOU	Main Oscillator Output
VDDOSC	Main Oscillator Power
VSSOSC	Main Oscillator Ground

## DC-to-DC Converter Interface (PWM)

- Provides two 96 kHz clock outputs with programmable duty ratio (from 1-in-16 to 15-in-16) that can be used to drive a positive or negative DC to DC converter

Table 14 shows the DC-to-DC Converter Interface pin assignments.

Table 14. DC-to-DC Converter Interface Pin Assignments

Pin Mnemonic	I/O	Pin Description
DRIVE[1:0]	I/O	PWM drive output
FB[1:0]	I	PWM feedback input

## Timers

- Internal (RTC) timer
- Two internal 16-bit programmable hardware count-down timers

## General Purpose Input/Output (GPIO)

- Three 8-bit and one 3-bit GPIO ports
- Supports scanning keyboard matrix

Table 15 shows the GPIO pin assignments.

Table 15. General Purpose Input/Output Pin Assignments

Pin Mnemonic	I/O	Pin Description
PA[7:0]	I/O	GPIO port A
PB[7:0]	I/O	GPIO port B
PD[0]/LEDFLSH (Note)	I/O	GPIO port D
PD[5:1]	I/O	GPIO port D
PD[7:6]/SDQM[1:0] (Note)	I/O	GPIO port D
PE[1:0]/BOOTSEL[1:0] (Note)	I/O	GPIO port E
PE[2]/CLKSEL (Note)	I/O	GPIO port E

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

## Hardware Debug Interface

- Full JTAG boundary scan and Embedded ICE<sup>®</sup> support

Table 16 shows the Hardware Debug Interface pin assignments.

Table 16. Hardware Debug Interface Pin Assignments

Pin Mnemonic	I/O	Pin Description
TCLK	I	JTAG clock
TDI	I	JTAG data input
TDO	O	JTAG data output
nTRST	I	JTAG async reset input
TMS	I	JTAG mode select

## LED Flasher

A dedicated LED flasher module can be used to generate a low frequency signal on Port D pin 0 for the purpose of blinking an LED without CPU intervention. The LED flasher feature is ideal as a visual annunciator in battery powered applications, such as a voice mail indicator on a portable phone or an appointment reminder on a PDA. Table 17 shows the LED Flasher pin assignments.

- Software adjustable flash period and duty cycle
- Operates from 32 kHz RTC clock
- Will continue to flash in IDLE and STANDBY states
- 4 mA drive current

Table 17. LED Flasher Pin Assignments

Pin Mnemonic	I/O	Pin Description
PD[0]/LEDFLSH (Note)	O	LED flasher driver

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

## Internal Boot ROM

The internal 128-byte Boot ROM facilitates download of saved code to the on-board SRAM/FLASH.

## Packaging

The EP7312 is available in a 208-pin LQFP package, 256-ball PBGA package, or a 204-ball TFBGA package.

## Pin Multiplexing

Table 18 shows the pin multiplexing of the DAI, SSI2 and the CODEC. The selection between SSI2 and the CODEC is controlled by the state of the SERSEL bit in SYSCON2. The choice between the SSI2, CODEC, and the DAI is controlled by the DAISEL bit in SYSCON3 (see the *EP7312 User's Manual* for more information).

**Table 18. DAI/SSI2/CODEC Pin Multiplexing**

Pin Mnemonic	I/O	DAI	SSI2	CODEC
SSICLK	I/O	SCLK	SSICLK	PCMCLK
SSITXDA	O	SDOUT	SSITXDA	PCMOUT
SSIRXDA	I	SDIN	SSIRXDA	PCMIN
SSITXFR	I/O	LRCK	SSITXFR	PCMSYNC
SSIRXFR	I	MCLKIN	SSIRXFR	p/u
BUZ	O	MCLKOUT		

Table 19 shows the pins that have been multiplexed in the EP7312.

**Table 19. Pin Multiplexing**

Signal	Block	Signal	Block
nMOE	Static Memory	nSDCAS	SDRAM
nMWE	Static Memory	nSDWE	SDRAM
WRITE	Static Memory	nSDRAS	SDRAM
A[27:15]	Static Memory	DRA[0:12]	SDRAM
A[14:13]	Static Memory	DRA[13:14]	SDRAM
PD[7:6]	GPIO	SDQM[1:0]	SDRAM
RUN	System Configuration	CLKEN	System Configuration
nMEDCHG	Interrupt Controller	nBROM	Boot ROM select
PD[0]	GPIO	LEDFLSH	LED Flasher
PE[1:0]	GPIO	BOOTSEL[1:0]	System Configuration
PE[2]	GPIO	CLKSEL	System Configuration

## System Design

As shown in system block diagram, simply adding desired memory and peripherals to the highly integrated EP7312

completes a low-power system solution. All necessary interface logic is integrated on-chip.

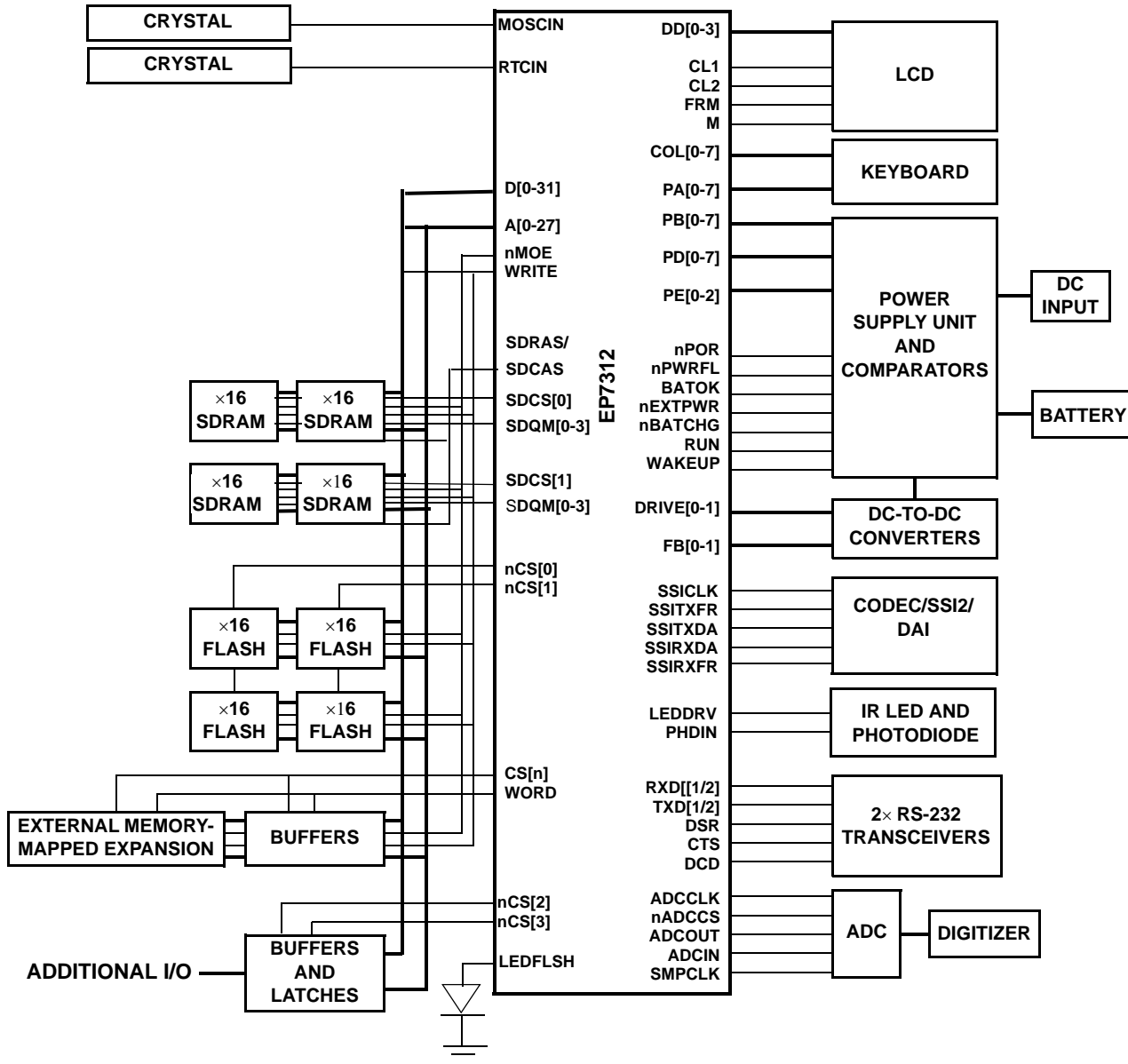


Figure 1. A Fully-Configured EP7312-Based System

Note: A system can only use one of the following peripheral interfaces at any given time: SSI2, CODEC or DAI.

## ELECTRICAL SPECIFICATIONS

### Absolute Maximum Ratings

DC Core, PLL, and RTC Supply Voltage	2.9 V
DC I/O Supply Voltage (Pad Ring)	3.6 V
DC Pad Input Current	±10 mA/pin; ±100 mA cumulative
Storage Temperature, No Power	-40°C to +125°C

### Recommended Operating Conditions

DC core, PLL, and RTC Supply Voltage	2.5 V ± 0.2 V
DC I/O Supply Voltage (Pad Ring)	2.3 V - 3.5 V
DC Input / Output Voltage	O-I/O supply voltage
Operating Temperature	Extended -20°C to +70°C; Commercial 0°C to +70°C; Industrial -40°C to +85°C

### DC Characteristics

All characteristics are specified at  $V_{DDCORE} = 2.5$  V,  $V_{DDIO} = 3.3$  V and  $V_{SS} = 0$  V over an operating temperature of 0°C to +70°C for all frequencies of operation. The current consumption figures have test conditions specified per parameter.”

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
VIH	CMOS input high voltage	$0.65 \times V_{DDIO}$	-	$V_{DDIO} + 0.3$	V	$V_{DDIO} = 2.5$ V
VIL	CMOS input low voltage	$V_{SS} - 0.3$	-	$0.25 \times V_{DDIO}$	V	$V_{DDIO} = 2.5$ V
VT+	Schmitt trigger positive going threshold	-	-	2.1	V	
VT-	Schmitt trigger negative going threshold	0.8	-	-	V	
Vhst	Schmitt trigger hysteresis	0.1	-	0.4	V	VIL to VIH
VOH	CMOS output high voltage <sup>a</sup>	$V_{DD} - 0.2$	-	-	V	IOH = 0.1 mA
	Output drive 1 <sup>a</sup>	2.5	-	-	V	IOH = 4 mA
	Output drive 2 <sup>a</sup>	2.5	-	-	V	IOH = 12 mA
VOL	CMOS output low voltage <sup>a</sup>	-	-	0.3	V	IOL = -0.1 mA
	Output drive 1 <sup>a</sup>	-	-	0.5	V	IOL = -4 mA
	Output drive 2 <sup>a</sup>	-	-	0.5	V	IOL = -12 mA
IIN	Input leakage current	-	-	1.0	µA	$V_{IN} = V_{DD}$ or GND
IOZ	Bidirectional 3-state leakage current <sup>b c</sup>	25	-	100	µA	$V_{OUT} = V_{DD}$ or GND
CIN	Input capacitance	8	-	10.0	pF	
COUT	Output capacitance	8	-	10.0	pF	

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
CI/O	Transceiver capacitance	8	-	10.0	pF	
$IDD_{STANDBY}$ @ 25 C	Standby current consumption <sup>1</sup> Core, Osc, RTC @2.5 V I/O @ 3.3 V	- -	77 41	- -	$\mu$ A	Only nPOR, nPWRFAIL, nURESET, PE0, PE1, and RTS are driven, while all other float, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V
$IDD_{STANDBY}$ @ 70 C	Standby current consumption <sup>1</sup> Core, Osc, RTC @2.5 V I/O @ 3.3 V	- -	- -	570 111	$\mu$ A	Only nPOR, nPWRFAIL, nURESET, PE0, PE1, and RTS are driven, while all other float, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V
$IDD_{STANDBY}$ @ 85 C	Standby current consumption <sup>1</sup> Core, Osc, RTC @2.5 V I/O @ 3.3 V	- -	- -	1693 163	$\mu$ A	Only nPOR, nPWRFAIL, nURESET, PE0, PE1, and RTS are driven, while all other float, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V
$IDD_{idle}$ at 74 MHz	Idle current consumption <sup>1</sup> Core, Osc, RTC @2.5 V I/O @ 3.3 V	- -	6 10	- -	mA	Both oscillators running, CPU static, Cache enabled, LCD disabled, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V
$IDD_{IDLE}$ at 90 MHz	Idle current consumption <sup>1</sup> Core, Osc, RTC @2.5 V I/O @ 3.3 V	- -	7 11	- -	mA	Both oscillators running, CPU static, Cache enabled, LCD disabled, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V
$VDD_{STANDBY}$	Standby supply voltage	2.0	-	-	V	Minimum standby voltage for state retention, internal SRAM cache, and RTC operation only

- Refer to the strength column in the pin assignment tables for all package types.
- Assumes buffer has no pull-up or pull-down resistors.
- The leakage value given assumes that the pin is configured as an input pin but is not currently being driven.

Note: 1) Total power consumption =  $IDD_{CORE} \times 2.5$  V +  $IDD_{IO} \times 3.3$  V

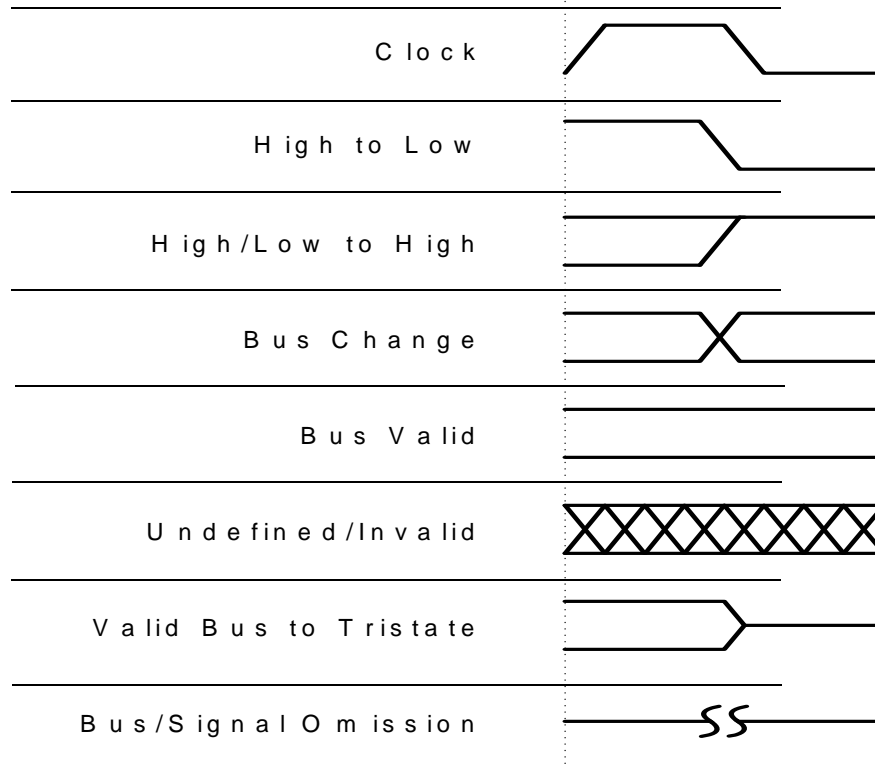
2) A typical design will provide 3.3 V to the I/O supply (i.e.,  $V_{DDIO}$ ), and 2.5 V to the remaining logic. This is to allow the I/O to be compatible with 3.3 V powered external logic (i.e., 3.3 V SDRAMs).

2) Pull-up current = 50  $\mu$ A typical at  $V_{DD} = 3.3$  V.

## Timings

### Timing Diagram Conventions

This data sheet contains timing diagrams. The following key explains the components used in these diagrams. Any variations are clearly labelled when they occur. Therefore, no additional meaning should be attached unless specifically stated.



**Figure 2. Legend for Timing Diagrams**

### Timing Conditions

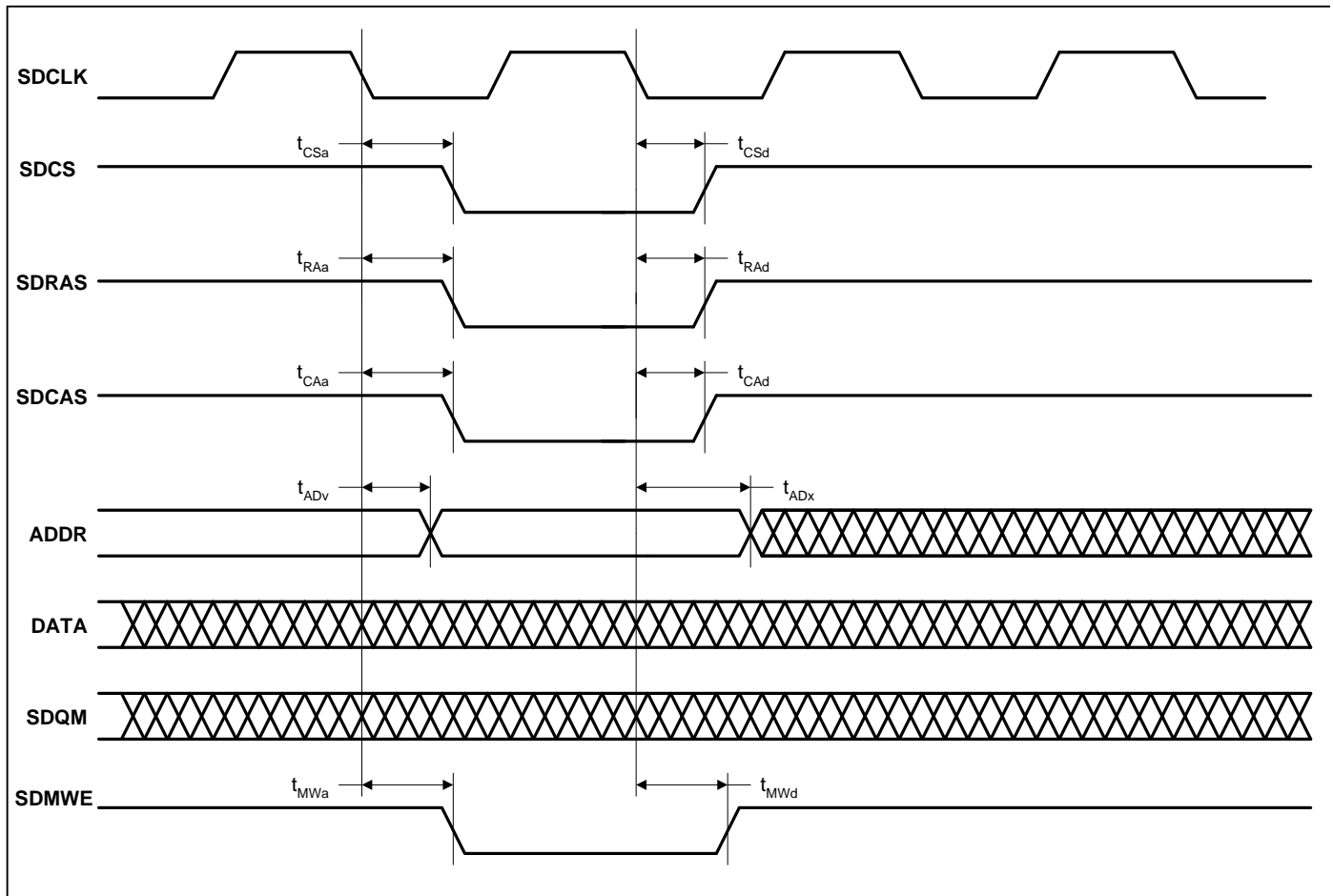
Unless specified otherwise, the following conditions are true for all timing measurements. All characteristics are specified at  $V_{DDIO} = 3.1 - 3.5 \text{ V}$  and  $V_{SS} = 0 \text{ V}$  over an operating temperature of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ . Pin loadings is  $50 \text{ pF}$ . The timing values are referenced to  $1/2 V_{DD}$ .

## SDRAM Interface

Figure 3 through Figure 6 define the timings associated with all phases of the SDRAM. The following table contains the values for the timings of each of the SDRAM modes.

Parameter	Symbol	Min	Typ	Max	Unit
SDCLK falling edge to SDCS assert delay time	$t_{CSa}$	0	2	4	ns
SDCLK falling edge to SDCS deassert delay time	$t_{CSd}$	-3	2	10	ns
SDCLK falling edge to SDRAS assert delay time	$t_{RAa}$	1	3	7	ns
SDCLK falling edge to SDRAS deassert delay time	$t_{RA d}$	-3	1	10	ns
SDCLK falling edge to SDRAS invalid delay time	$t_{RAnv}$	2	4	7	ns
SDCLK falling edge to SDCAS assert delay time	$t_{CAa}$	-2	2	5	ns
SDCLK falling edge to SDCAS deassert delay time	$t_{CA d}$	-5	0	3	ns
SDCLK falling edge to ADDR transition time	$t_{ADv}$	-3	1	5	ns
SDCLK falling edge to ADDR invalid delay time	$t_{ADx}$	-2	2	5	ns
SDCLK falling edge to SDMWE assert delay time	$t_{MWa}$	-3	1	5	ns
SDCLK falling edge to SDMWE deassert delay time	$t_{MWd}$	-4	0	4	ns
DATA transition to SDCLK falling edge time	$t_{DAs}$	2	-	-	ns
SDCLK falling edge to DATA transition hold time	$t_{DAh}$	1	-	-	ns
SDCLK falling edge to DATA transition delay time	$t_{DA d}$	0	-	15	ns



**SDRAM Load Mode Register Cycle**

**Figure 3. SDRAM Load Mode Register Cycle Timing Measurement**

- Note:
1. Timings are shown with CAS latency = 2
  2. The SDCLK signal may be phase shifted relative to the rest of the SDRAM control and data signals due to uneven loading. Designers should take care to ensure that delays between SDRAM control and data signals are approximately equal

### SDRAM Burst Read Cycle

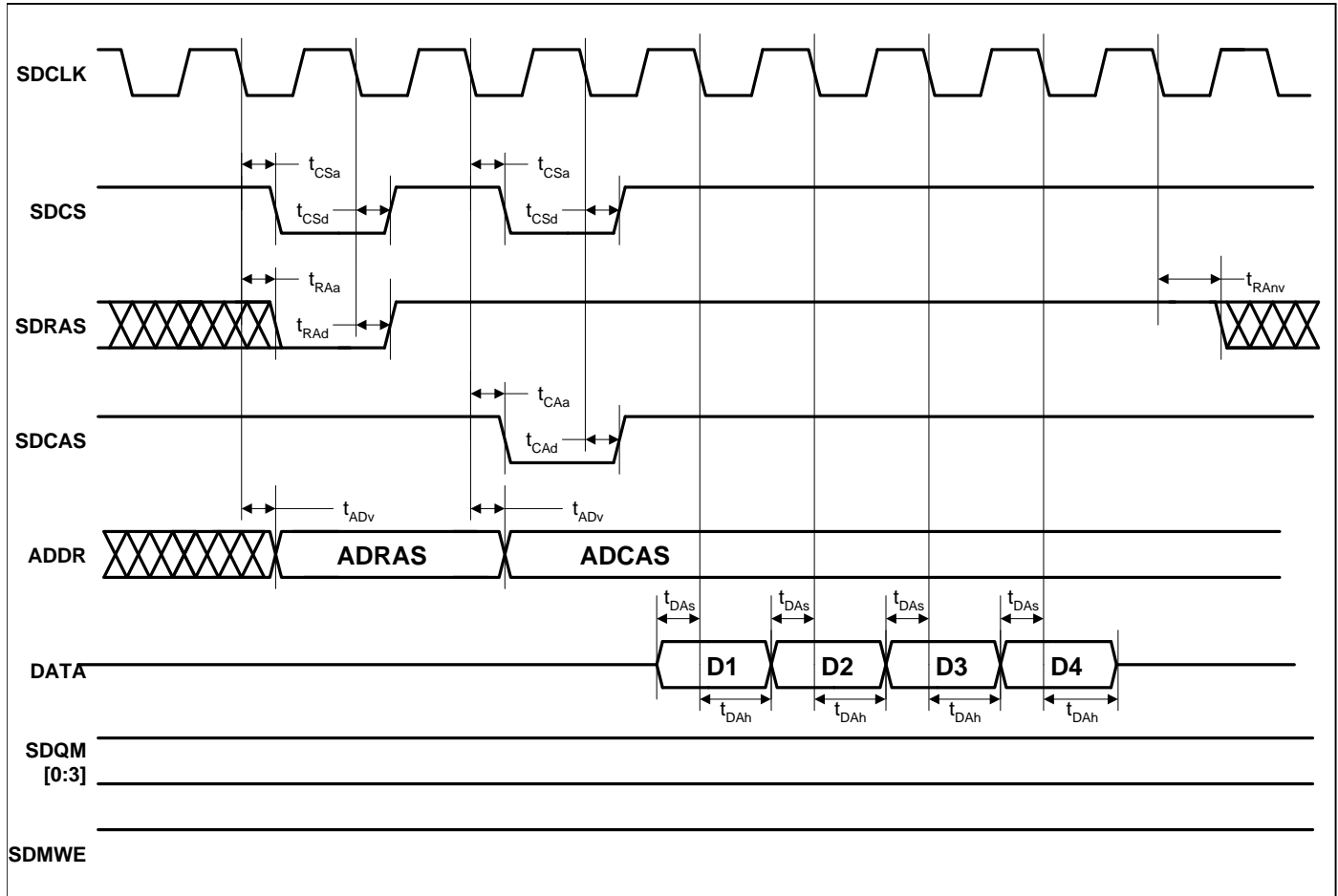
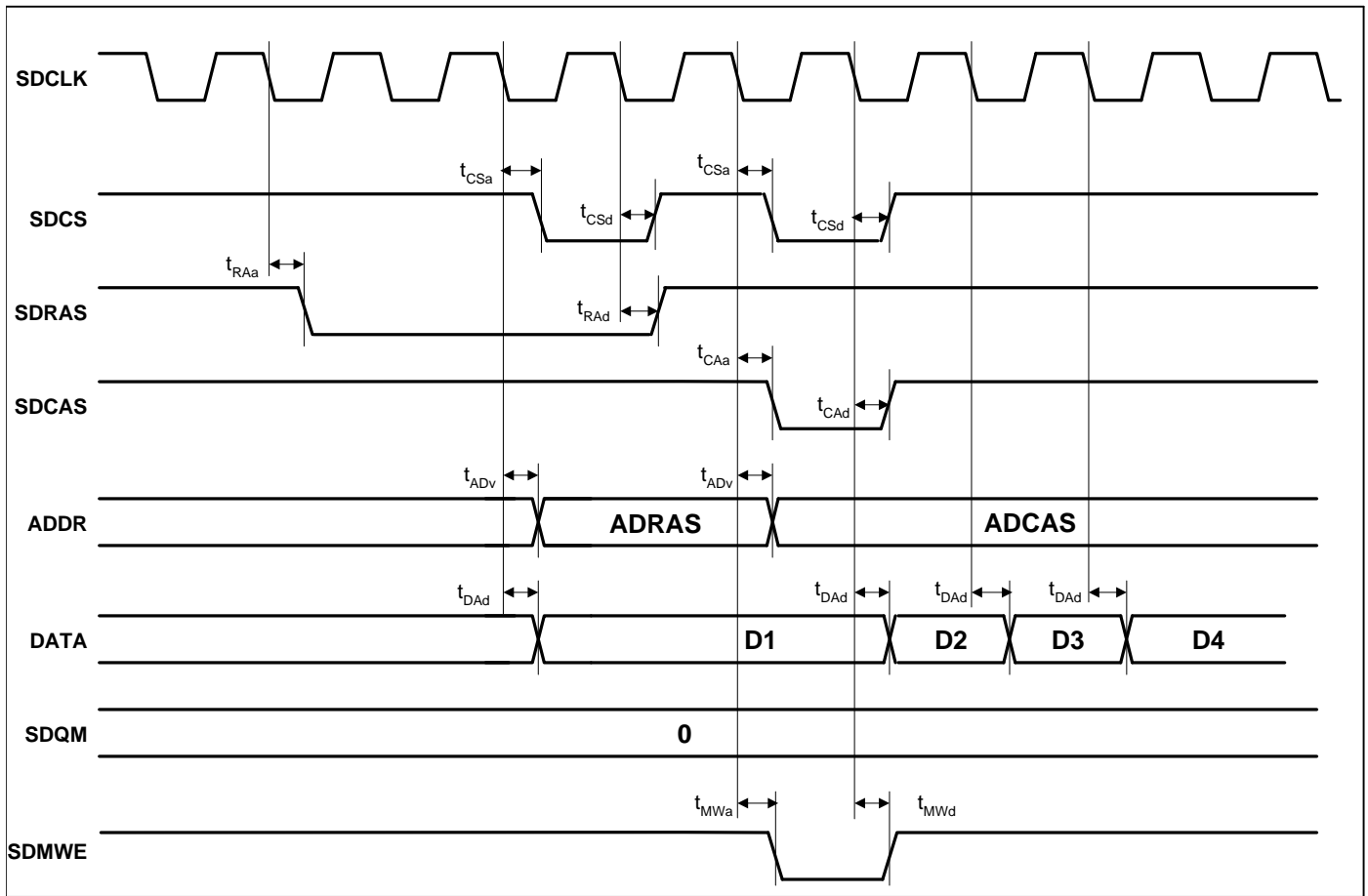


Figure 4. SDRAM Burst Read Cycle Timing Measurement

Note: 1. Timings are shown with CAS latency = 2  
2. The SDCLK signal may be phase shifted relative to the rest of the SDRAM control and data signals due to uneven loading. Designers should take care to ensure that delays between SDRAM control and data signals are approximately equal.

**SDRAM Burst Write Cycle**


**Figure 5. SDRAM Burst Write Cycle Timing Measurement**

- Note:
1. Timings are shown with CAS latency = 2
  2. The SDCLK signal may be phase shifted relative to the rest of the SDRAM control and data signals due to uneven loading. Designers should take care to ensure that delays between SDRAM control and data signals are approximately equal

## SDRAM Refresh Cycle

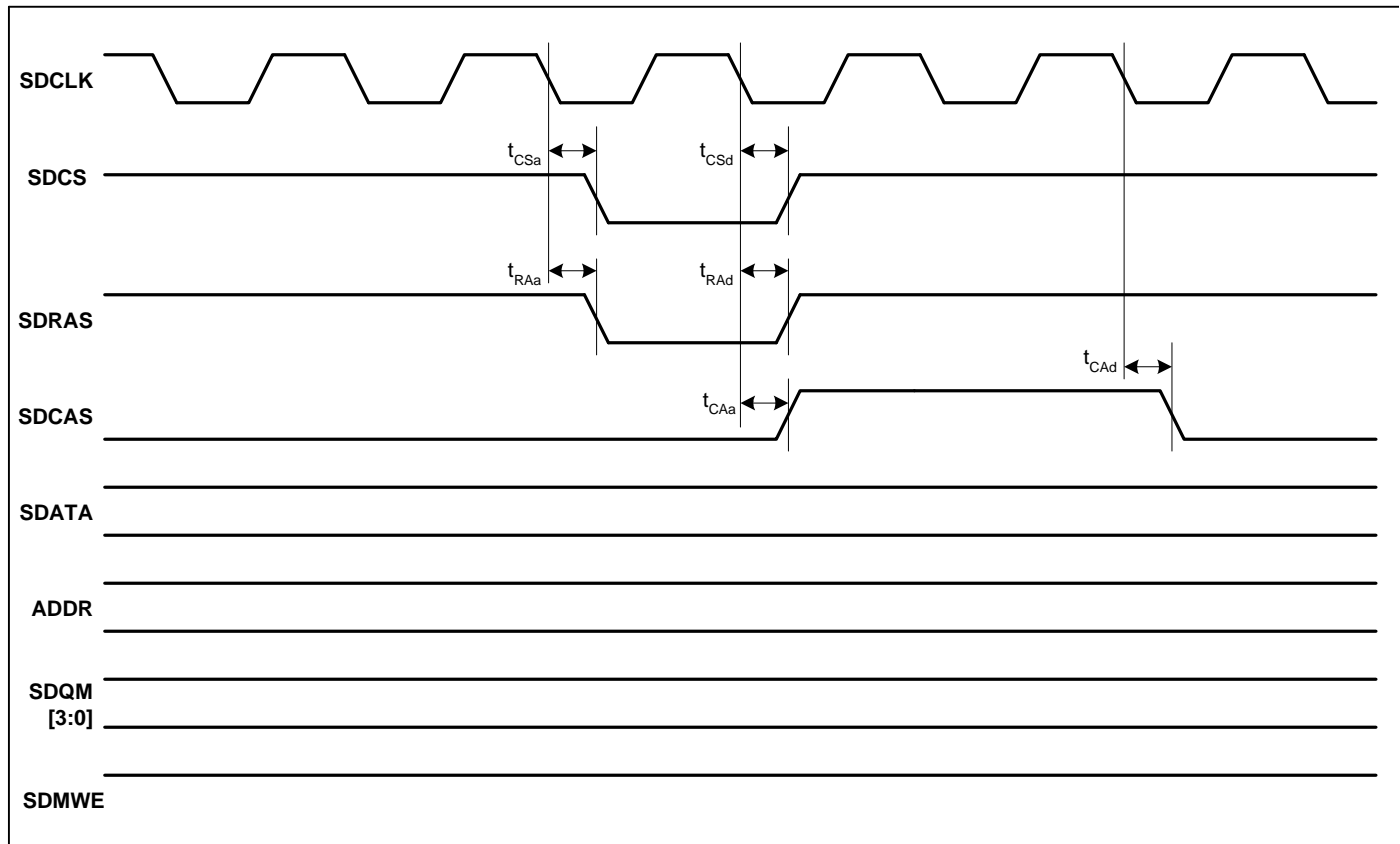


Figure 6. SDRAM Refresh Cycle Timing Measurement

- Note:
1. Timings are shown with CAS latency = 2
  2. The SDCLK signal may be phase shifted relative to the rest of the SDRAM control and data signals due to uneven loading. Designers should take care to ensure that delays between SDRAM control and data signals are approximately equal

## Static Memory

Figure 7 through Figure 10 define the timings associated with all phases of the Static Memory. The following table contains the values for the timings of each of the Static Memory modes.

Parameter	Symbol	Min	Typ	Max	Unit
EXPCLK rising edge to nCS assert delay time	$t_{CSd}$	2	8	20	ns
EXPCLK falling edge to nCS deassert hold time	$t_{CSh}$	2	7	20	ns
EXPCLK rising edge to A assert delay time	$t_{Ad}$	4	9	16	ns
EXPCLK falling edge to A deassert hold time	$t_{Ah}$	3	10	19	ns
EXPCLK rising edge to nMWE assert delay time	$t_{MWd}$	3	6	10	ns
EXPCLK rising edge to nMWE deassert hold time	$t_{MWh}$	3	6	10	ns
EXPCLK falling edge to nMOE assert delay time	$t_{MOEd}$	3	7	10	ns
EXPCLK falling edge to nMOE deassert hold time	$t_{MOEh}$	2	7	10	ns
EXPCLK falling edge to HALFWORD deassert delay time	$t_{HWd}$	2	8	20	ns
EXPCLK falling edge to WORD assert delay time	$t_{WDd}$	2	8	16	ns
EXPCLK rising edge to data valid delay time	$t_{Dv}$	8	13	21	ns
EXPCLK falling edge to data invalid delay time	$t_{Dnv}$	6	15	30	ns
Data setup to EXPCLK falling edge time	$t_{Ds}$	-	-	1	ns
EXPCLK falling edge to data hold time	$t_{Dh}$	-	-	3	ns
EXPCLK rising edge to WRITE assert delay time	$t_{WRd}$	5	11	23	ns
EXPREADY setup to EXPCLK falling edge time	$t_{EXs}$	-	-	0	ns
EXPCLK falling edge to EXPREADY hold time	$t_{EXh}$	-	-	0	ns

### Static Memory Single Read Cycle

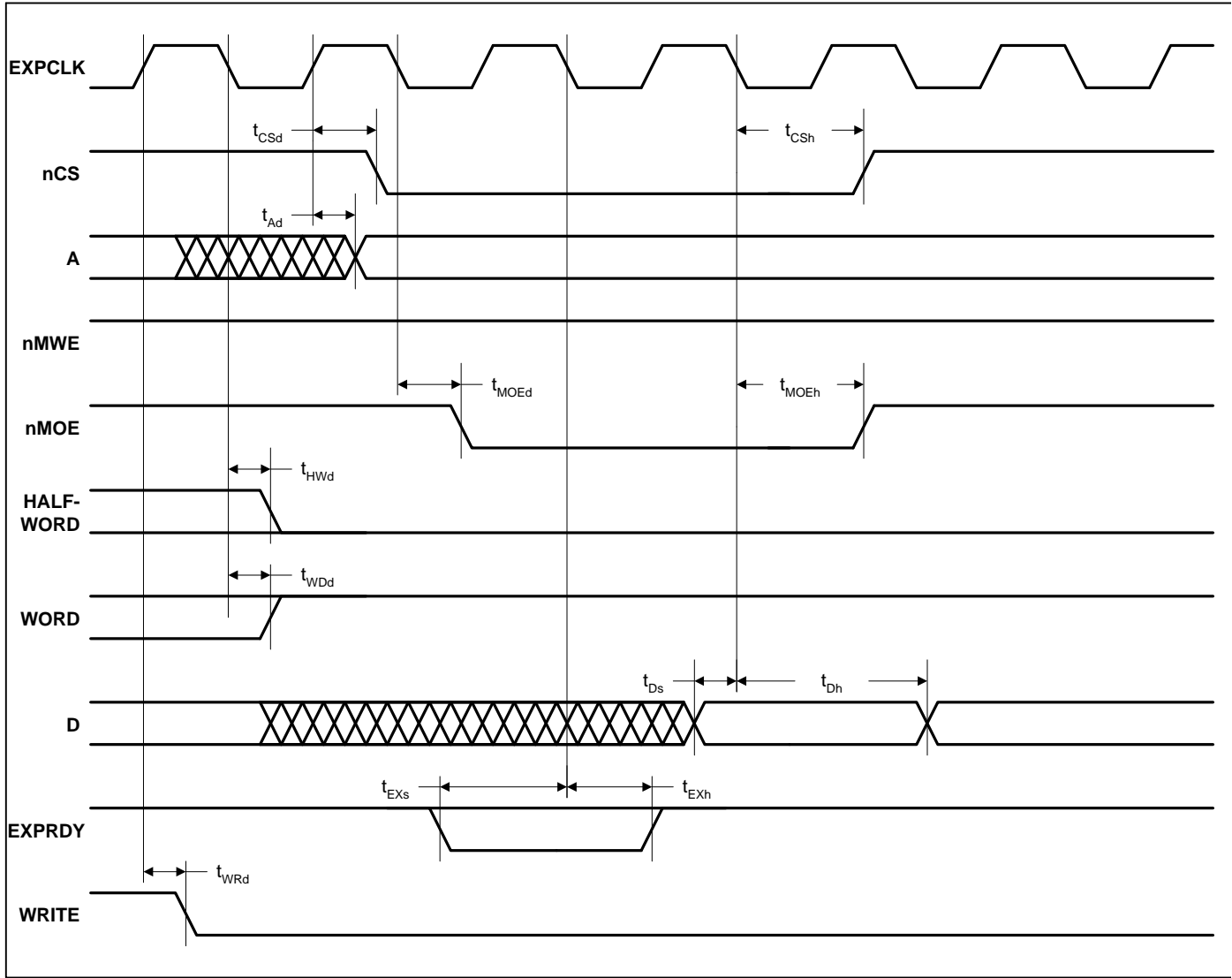
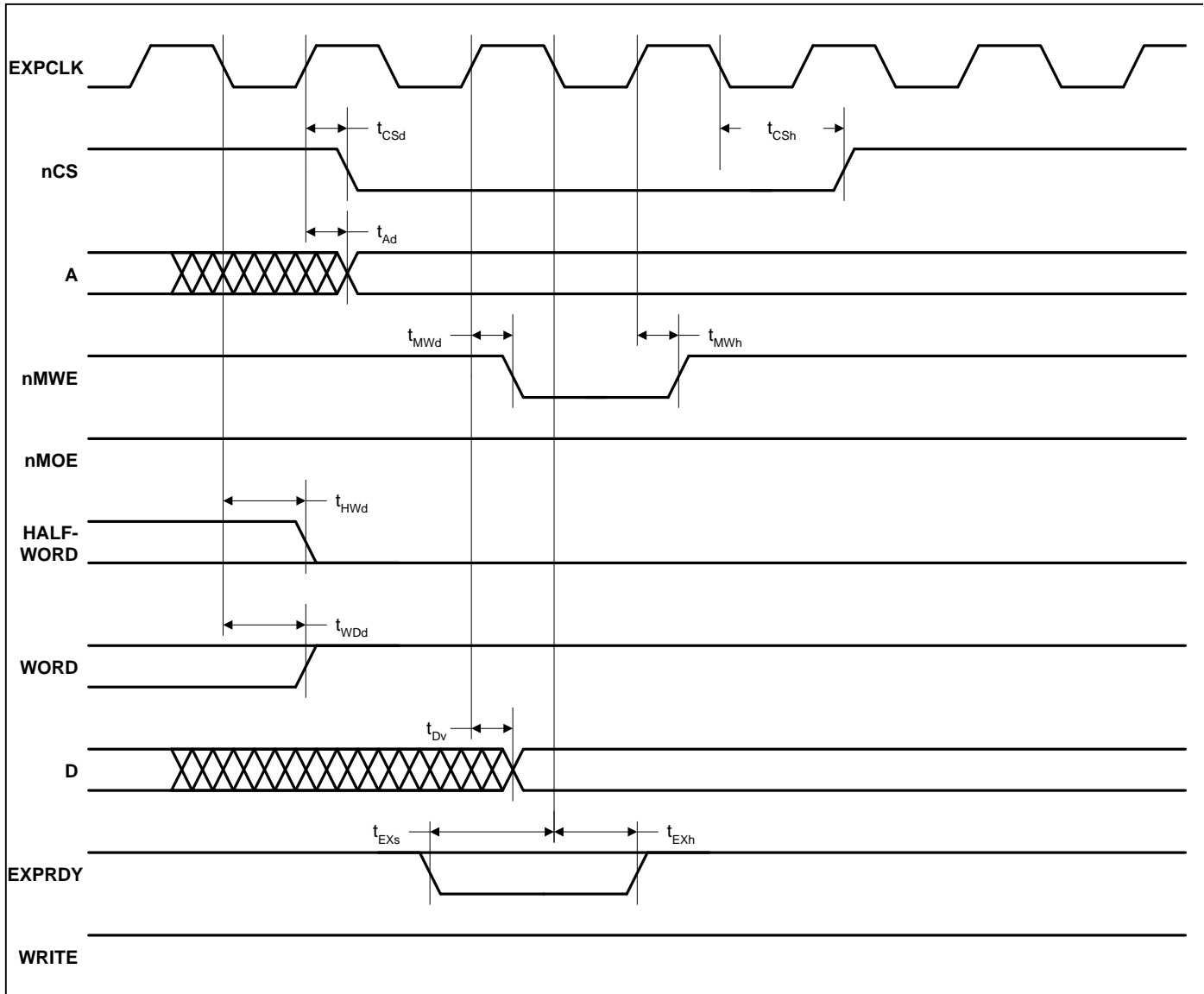


Figure 7. Static Memory Single Read Cycle Timing Measurement

Note: 1. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.  
2. Address, Halfword, Word, and Write hold state until next cycle.

**Static Memory Single Write Cycle**

**Figure 8. Static Memory Single Write Cycle Timing Measurement**

- Note:
1. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
  2. Zero wait states for sequential writes is not permitted for memory devices which use nMWE pin, as this cannot be driven with valid timing under zero wait state conditions.
  3. Address, Data, Halfword, Word, and Write hold state until next cycle.

## Static Memory Burst Read Cycle

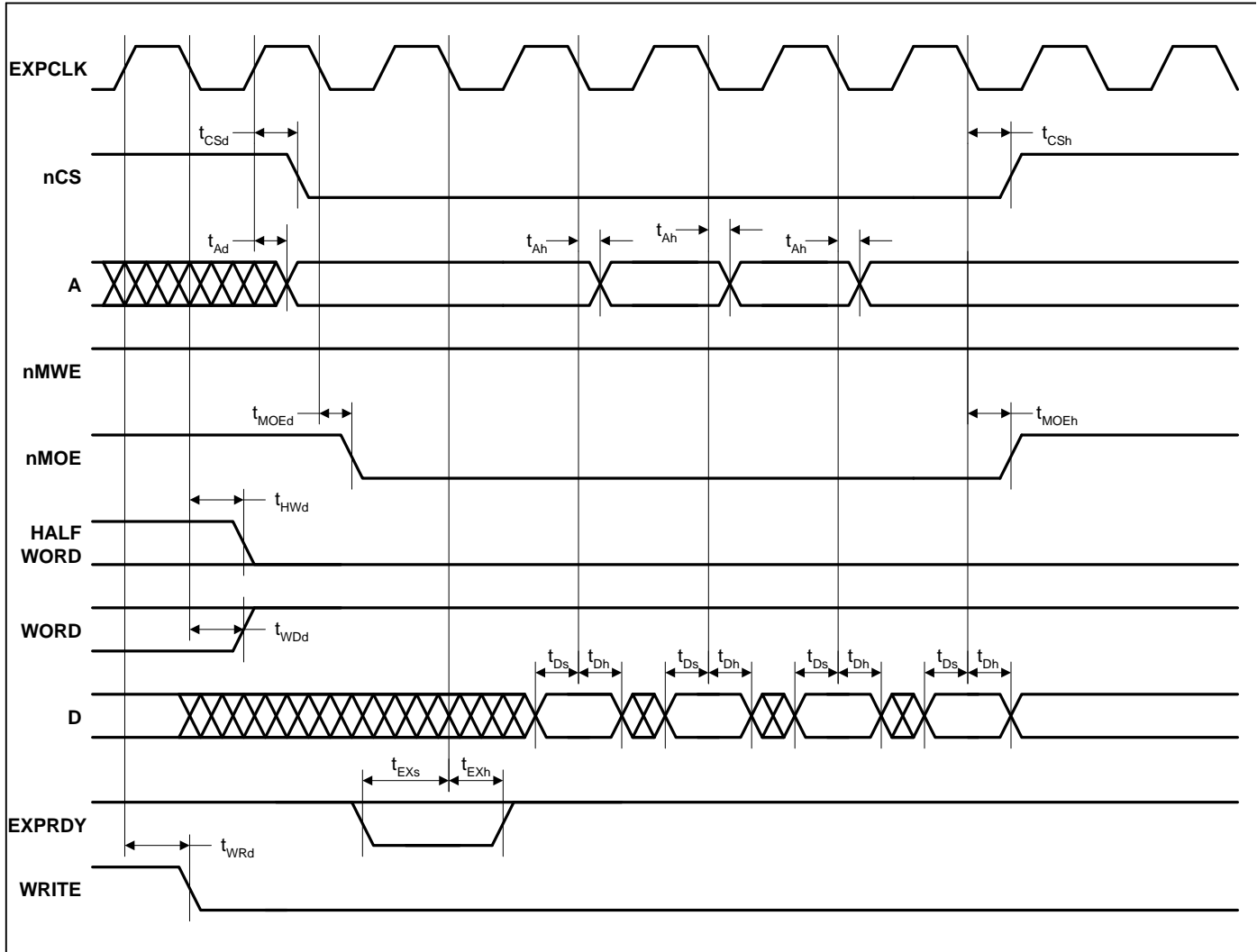
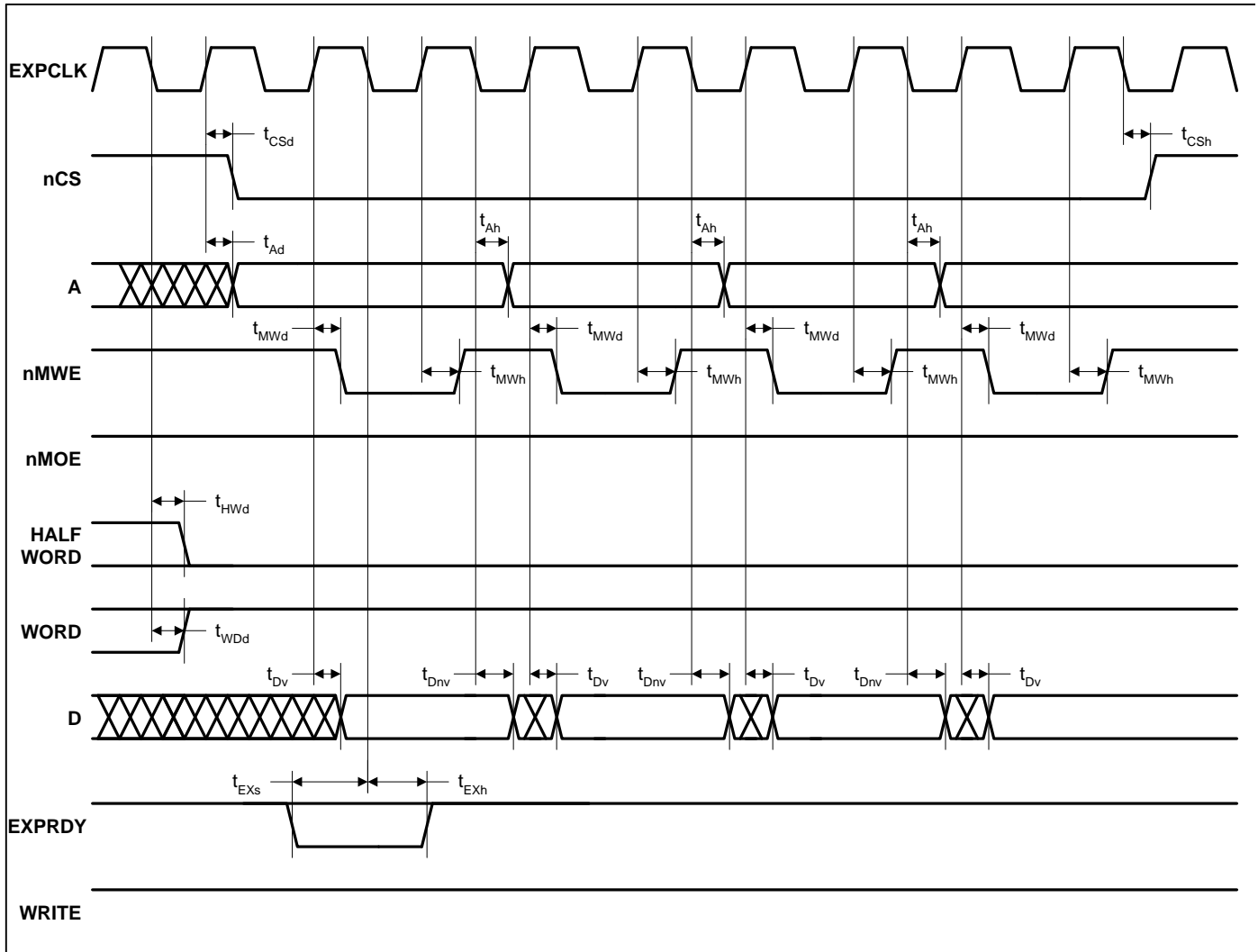


Figure 9. Static Memory Burst Read Cycle Timing Measurement

- Note:
- Four cycles are shown in the above diagram (minimum wait states, 1-0-0-0). This is the maximum number of consecutive cycles that can be driven. The number of consecutive cycles can be programmed from 2 to 4, inclusively.
  - The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
  - Consecutive reads with sequential access enabled are identical except that the sequential access wait state field is used to determine the number of wait states, and no idle cycles are inserted between successive non-sequential ROM/expansion cycles. This improves performance so the SQAEN bit should always be set where possible.
  - Address, Halfword, Word, and Write hold state until next cycle.



**Static Memory Burst Write Cycle**

**Figure 10. Static Memory Burst Write Cycle Timing Measurement**

- Note:
1. Four cycles are shown in the above diagram (minimum wait states, 1-1-1-1). This is the maximum number of consecutive cycles that can be driven. The number of consecutive cycles can be programmed from 2 to 4, inclusively.
  2. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
  3. Zero wait states for sequential writes is not permitted for memory devices which use nMWE pin, as this cannot be driven with valid timing under zero wait state conditions.
  4. Address, Data, Halfword, Word, and Write hold state until next cycle.

## SSI1 Interface

Parameter	Symbol	Min	Max	Unit
ADCCLK falling edge to nADCCSS deassert delay time	$t_{Cd}$	9	10	ms
ADCIN data setup to ADCCLK rising edge time	$t_{INs}$	-	15	ns
ADCIN data hold from ADCCLK rising edge time	$t_{INh}$	-	14	ns
ADCCLK falling edge to data valid delay time	$t_{Ovd}$	-7	13	ns
ADCCLK falling edge to data invalid delay time	$t_{Od}$	-2	3	ns

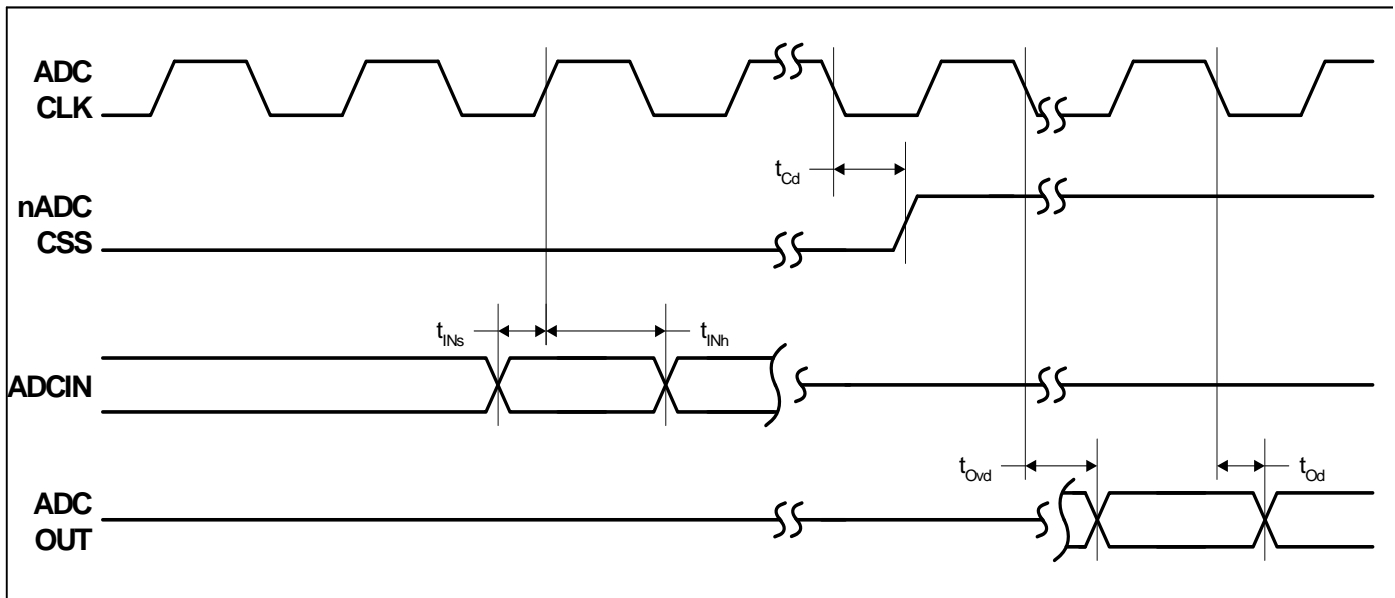


Figure 11. SSI1 Interface Timing Measurement

## SSI2 Interface

Parameter	Symbol	Min	Max	Unit
SSICLK period (slave mode)	$t_{clk\_per}$	185	2050	ns
SSICLK high time	$t_{clk\_high}$	925	1025	ns
SSICLK low time	$t_{clk\_low}$	925	1025	ns
SSICLK rise/fall time	$t_{clkrf}$	3	18	ns
SSICLK rising edge to RX and/or TX frame sync high time	$t_{FRd}$	-	3	ns
SSICLK rising edge to RX and/or TX frame sync low time	$t_{FRa}$	-	8	ns
SSIRXFR and/or SSITXFR period	$t_{FR\_per}$	960	990	ns
SSIRXDA setup to SSICLK falling edge time	$t_{RXs}$	3	7	ns
SSIRXDA hold from SSICLK falling edge time	$t_{RXh}$	3	7	ns
SSICLK rising edge to SSITXDA data valid delay time	$t_{TXd}$	-	2	ns
SSITXDA valid time	$t_{TXv}$	960	990	ns

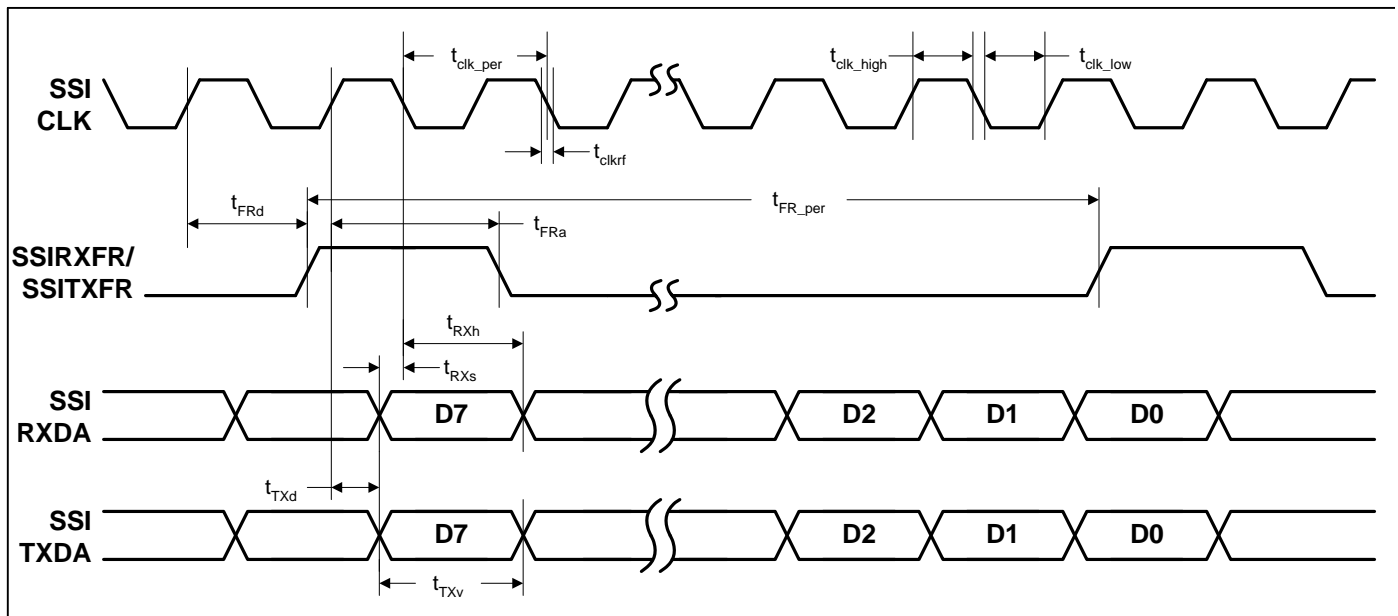


Figure 12. SSI2 Interface Timing Measurement

## LCD Interface

Parameter	Symbol	Min	Max	Unit
CL[2] falling to CL[1] rising delay time	$t_{CL1d}$	- 10	25	ns
CL[1] falling to CL[2] rising delay time	$t_{CL2d}$	80	3,475	ns
CL[1] falling to FRM transition time	$t_{FRMd}$	300	10,425	ns
CL[1] falling to M transition time	$t_{Md}$	- 10	20	ns
CL[2] rising to DD (display data) transition time	$t_{DDd}$	- 10	20	ns

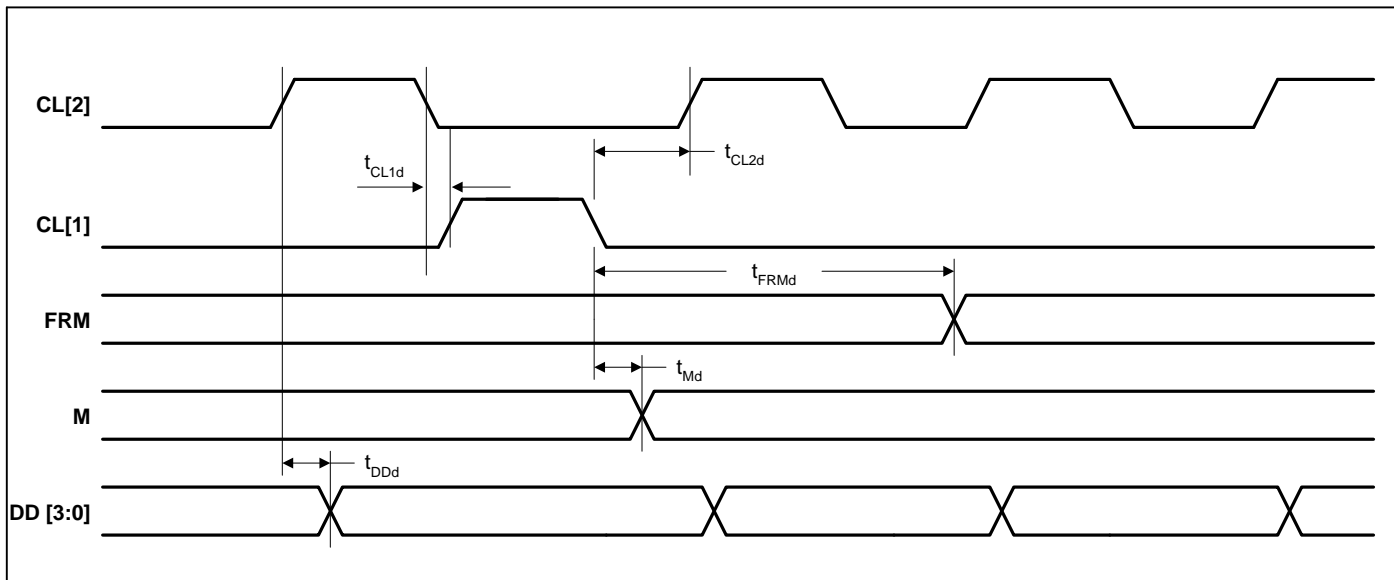
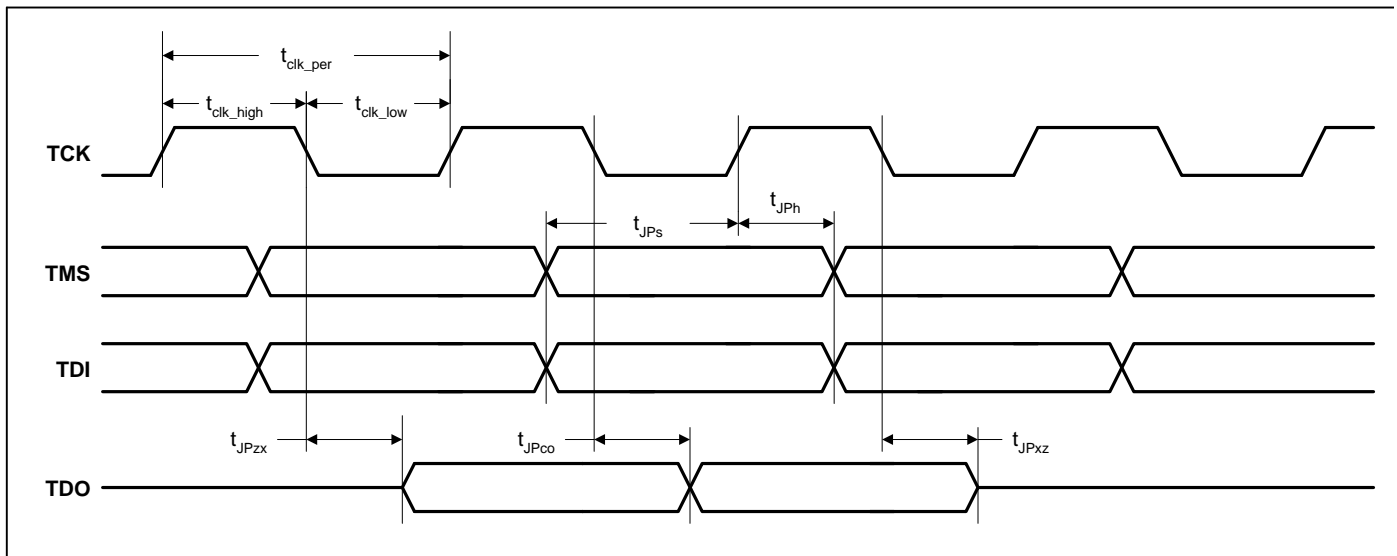


Figure 13. LCD Controller Timing Measurement

## JTAG Interface

Parameter	Symbol	Min	Max	Units
TCK clock period	$t_{clk\_per}$	2	-	ns
TCK clock high time	$t_{clk\_high}$	1	-	ns
TCK clock low time	$t_{clk\_low}$	1	-	ns
JTAG port setup time	$t_{JP_s}$	-	0	ns
JTAG port hold time	$t_{JP_h}$	-	3	ns
JTAG port clock to output	$t_{JP_{co}}$	-	10	ns
JTAG port high impedance to valid output	$t_{JP_{zx}}$	-	12	ns
JTAG port valid output to high impedance	$t_{JP_{xz}}$	-	19	ns



**Figure 14. JTAG Timing Measurement**

## Packages

### 208-Pin LQFP Package Characteristics

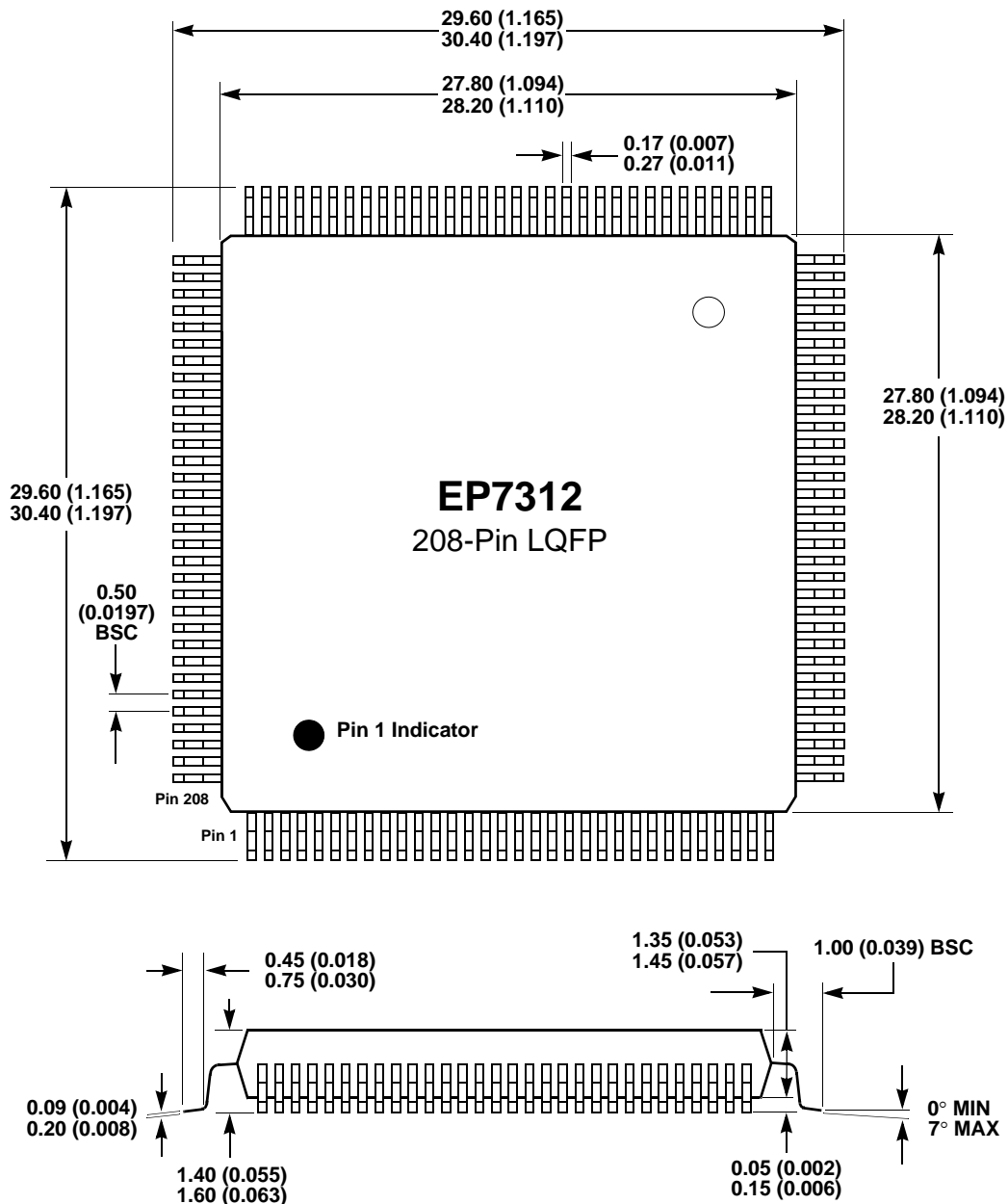


Figure 15. 208-Pin LQFP Package Outline Drawing

- Note:
- 1) Dimensions are in millimeters (inches), and controlling dimension is millimeter.
  - 2) Drawing above does not reflect exact package pin count.
  - 3) Before beginning any new design with this device, please contact Cirrus Logic for the latest package information.
  - 4) For pin locations, please see [Figure 16](#). For pin descriptions see the EP7312 User's Manual.

### 208-Pin LQFP Pin Diagram

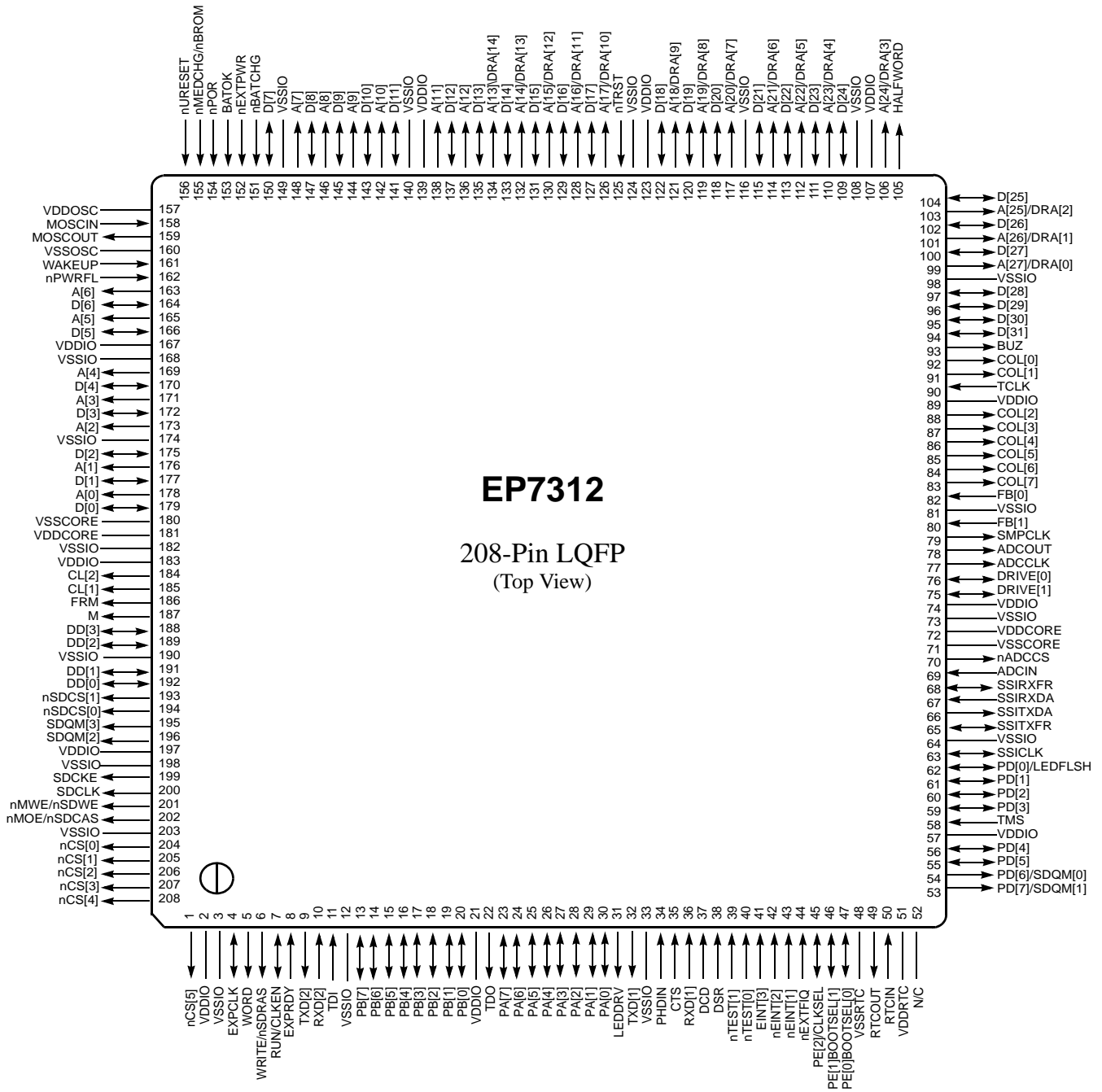


Figure 16. 208-Pin LQFP (Low Profile Quad Flat Pack) Pin Diagram

Note: 1. N/C should not be grounded but left as no connects.

## 208-Pin LQFP Numeric Pin Listing

Table 20. 208-Pin LQFP Numeric Pin Listing

Pin No.	Signal	Strength †	Reset State	Type	Description
1	nCS[5]	1	Low	O	Chip select 5
2	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
3	VSSIO			Pad Gnd	I/O ground
4	EXPCLK	1		I	Expansion clock input
5	WORD	1	Low	O	Word access select output
6	WRITE/nSDRAS	1	Low	O	Transfer direction / SDRAM RAS signal output
7	RUN/CLKEN	1	Low	O	Run output / clock enable output
8	EXPRDY	1		I	Expansion port ready input
9	TXD[2]	1	High	O	UART 2 transmit data output
10	RXD[2]			I	UART 2 receive data input
11	TDI	with p/u*		I	JTAG data input
12	VSSIO			Pad Gnd	I/O ground
13	PB[7]	1	Input †	I/O	GPIO port B
14	PB[6]	1	Input †	I/O	GPIO port B
15	PB[5]	1	Input †	I/O	GPIO port B
16	PB[4]	1	Input †	I/O	GPIO port B
17	PB[3]	1	Input †	I/O	GPIO port B
18	PB[2]	1	Input †	I/O	GPIO port B
19	PB[1]	1	Input †	I/O	GPIO port B
20	PB[0]	1	Input †	I/O	GPIO port B
21	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
22	TDO	1	Input †	O	JTAG data out
23	PA[7]	1	Input †	I/O	GPIO port A
24	PA[6]	1	Input †	I/O	GPIO port A
25	PA[5]	1	Input †	I/O	GPIO port A
26	PA[4]	1	Input †	I/O	GPIO port A
27	PA[3]	1	Input †	I/O	GPIO port A
28	PA[2]	1	Input †	I/O	GPIO port A
29	PA[1]	1	Input †	I/O	GPIO port A
30	PA[0]	1	Input †	I/O	GPIO port A
31	LEDDRV	1	Low	O	IR LED drive
32	TXD[1]	1	High	O	UART 1 transmit data out
33	VSSIO	1	High	Pad Gnd	I/O ground
34	PHDIN			I	Photodiode input
35	CTS			I	UART 1 clear to send input
36	RXD[1]			I	UART 1 receive data input
37	DCD			I	UART 1 data carrier detect



**Table 20. 208-Pin LQFP Numeric Pin Listing (Continued)**

Pin No.	Signal	Strength †	Reset State	Type	Description
38	DSR			I	UART 1 data set ready input
39	nTEST[1]	With p/u*		I	Test mode select input
40	nTEST[0]	With p/u*		I	Test mode select input
41	EINT[3]			I	External interrupt
42	nEINT[2]			I	External interrupt input
43	nEINT[1]			I	External interrupt input
44	nEXTFIQ			I	External fast interrupt input
45	PE[2]/CLKSEL	1	Input †	I/O	GPIO port E / clock input mode select
46	PE[1]/BOOTSEL[1]	1	Input †	I/O	GPIO port E / boot mode select
47	PE[0]/BOOTSEL[0]	1	Input †	I/O	GPIO port E / Boot mode select
48	VSSRTC			RTC Gnd	Real time clock ground
49	RTCOUT			O	Real time clock oscillator output
50	RTCIN			I	Real time clock oscillator input
51	VDDRTC			RTC power	Real time clock power, 2.5 V
52	N/C				
53	PD[7]/SDQM[1]	1	Low	I/O	GPIO port D / SDRAM byte lane mask
54	PD[6]/SDQM[0]	1	Low	I/O	GPIO port D / SDRAM byte lane mask
55	PD[5]	1	Low	I/O	GPIO port D
56	PD[4]	1	Low	I/O	GPIO port D
57	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
58	TMS	with p/u*		I	JTAG mode select
59	PD[3]	1	Low	I/O	GPIO port D
60	PD[2]	1	Low	I/O	GPIO port D
61	PD[1]	1	Low	I/O	GPIO port D
62	PD[0]/LEDFLSH	1	Low	I/O	GPIO port D / LED blinker output
63	SSICLK	1	Input †	I/O	DAI/CODEC/SSI2 serial clock
64	VSSIO			Pad Gnd	I/O ground
65	SSITXFR	1	Low	I/O	DAI/CODEC/SSI2 serial clock
66	SSITXDA	1	Low	O	DAI/CODEC/SSI2 serial data output
67	SSIRXDA			I	DAI/CODEC/SSI2 serial data input
68	SSIRXFR		Input †	I/O	DAI/CODEC/SSI2 frame sync
69	ADCIN			I	SSI1 ADC serial input
70	nADCCS	1	High	O	SSI1 ADC chip select
71	VSSCORE			Core ground	Core ground
72	VDDCORE			Core Pwr	Core power, 2.5 V
73	VSSIO			Pad Gnd	I/O ground
74	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
75	DRIVE[1]	2	High / Low	I/O	PWM drive output
76	DRIVE[0]	2	High / Low	I/O	PWM drive output
77	ADCCLK	1	Low	O	SSI1 ADC serial clock
78	ADCOUT	1	Low	O	SSI1 ADC serial data output

Table 20. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Strength †	Reset State	Type	Description
79	SMPCLK	1	Low	O	SSI1 ADC sample clock
80	FB[1]			I	PWM feedback input
81	VSSIO			Pad Gnd	I/O ground
82	FB[0]			I	PWM feedback input
83	COL[7]	1	High	O	Keyboard scanner column drive
84	COL[6]	1	High	O	Keyboard scanner column drive
85	COL[5]	1	High	O	Keyboard scanner column drive
86	COL[4]	1	High	O	Keyboard scanner column drive
87	COL[3]	1	High	O	Keyboard scanner column drive
88	COL[2]	1	High	O	Keyboard scanner column drive
89	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
90	TCLK			I	JTAG clock
91	COL[1]	1	High	O	Keyboard scanner column drive
92	COL[0]	1	High	O	Keyboard scanner column drive
93	BUZ	1	Low	O	Buzzer drive output
94	D[31]	1	Low	I/O	Data I/O
95	D[30]	1	Low	I/O	Data I/O
96	D[29]	1	Low	I/O	Data I/O
97	D[28]	1	Low	I/O	Data I/O
98	VSSIO			Pad Gnd	I/O ground
99	A[27]/DRA[0]	2	Low	O	System byte address / SDRAM address
100	D[27]	1	Low	I/O	Data I/O
101	A[26]/DRA[1]	2	Low	O	System byte address / SDRAM address
102	D[26]	1	Low	I/O	Data I/O
103	A[25]/DRA[2]	2	Low	O	System byte address / SDRAM address
104	D[25]	1	Low	I/O	Data I/O
105	HALFWORD	1	Low	O	Halfword access select output
106	A[24]/DRA[3]	1	Low	O	System byte address / SDRAM address
107	VDDIO		—	Pad Pwr	Digital I/O power, 3.3 V
108	VSSIO		—	Pad Gnd	I/O ground
109	D[24]	1	Low	I/O	Data I/O
110	A[23]/DRA[4]	1	Low	O	System byte address / SDRAM address
111	D[23]	1	Low	I/O	Data I/O
112	A[22]/DRA[5]	1	Low	O	System byte address / SDRAM address
113	D[22]	1	Low	I/O	Data I/O
114	A[21]/DRA[6]	1	Low	O	System byte address / SDRAM address
115	D[21]	1	Low	I/O	Data I/O
116	VSSIO			Pad Gnd	I/O ground
117	A[20]/DRA[7]	1	Low	O	System byte address / SDRAM address

**Table 20. 208-Pin LQFP Numeric Pin Listing (Continued)**

Pin No.	Signal	Strength †	Reset State	Type	Description
118	D[20]	1	Low	I/O	Data I/O
119	A[19]/DRA[8]	1	Low	O	System byte address / SDRAM address
120	D[19]	1	Low	I/O	Data I/O
121	A[18]/DRA[9]	1	Low	O	System byte address / SDRAM address
122	D[18]	1	Low	I/O	Data I/O
123	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
124	VSSIO			Pad Gnd	I/O ground
125	nTRST			I	JTAG async reset input
126	A[17]/DRA[10]	1	Low	O	System byte address / SDRAM address
127	D[17]	1	Low	I/O	Data I/O
128	A[16]/DRA[11]	1	Low	O	System byte address / SDRAM address
129	D[16]	1	Low	I/O	Data I/O
130	A[15]/DRA[12]	1	Low	O	System byte address / SDRAM address
131	D[15]	1	Low	I/O	Data I/O
132	A[14]/DRA[13]	1	Low	O	System byte address / SDRAM address
133	D[14]	1	Low	I/O	Data I/O
134	A[13]/DRA[14]	1	Low	O	System byte address / SDRAM address
135	D[13]	1	Low	I/O	Data I/O
136	A[12]	1	Low	O	System byte address
137	D[12]	1	Low	I/O	Data I/O
138	A[11]	1	Low	O	System byte address
139	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
140	VSSIO			Pad Gnd	I/O ground
141	D[11]	1	Low	I/O	Data I/O
142	A[10]	1	Low	O	System byte address
143	D[10]	1	Low	I/O	Data I/O
144	A[9]	1	Low	O	System byte address
145	D[9]	1	Low	I/O	Data I/O
146	A[8]	1	Low	O	System byte address
147	D[8]	1	Low	I/O	Data I/O
148	A[7]	1	Low	O	System byte address
149	VSSIO			Pad Gnd	I/O ground
150	D[7]	1	Low	I/O	Data I/O
151	nBATCHG			I	Battery changed sense input
152	nEXTPWR			I	External power supply sense input
153	BATOK			I	Battery OK input
154	nPOR	Schmitt		I	Power-on reset input
155	nMEDCHG/nBROM			I	Media change interrupt input / internal ROM boot enable
156	nURESET	Schmitt		I	User reset input
157	VDDOSC			Oscillator Power	Oscillator power in, 2.5 V
158	MOSCIN			I	Main oscillator input
159	MOSCOUT			O	Main oscillator output
160	VSSOSC			Oscillator Ground	Oscillator Ground

Table 20. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Strength †	Reset State	Type	Description
161	WAKEUP	Schmitt		I	System wake up input
162	nPWRFL			I	Power fail sense input
163	A[6]	1	Low	O	System byte address
164	D[6]	1	Low	I/O	Data I/O
165	A[5]	1	Low	Out	System byte address
166	D[5]	1	Low	I/O	Data I/O
167	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
168	VSSIO			Pad Gnd	I/O ground
169	A[4]	1	Low	O	System byte address
170	D[4]	1	Low	I/O	Data I/O
171	A[3]	2	Low	O	System byte address
172	D[3]	1	Low	I/O	Data I/O
173	A[2]	2	Low	O	System byte address
174	VSSIO			Pad Gnd	I/O ground
175	D[2]	1	Low	I/O	Data I/O
176	A[1]	2	Low	O	System byte address
177	D[1]	1	Low	I/O	Data I/O
178	A[0]	2	Low	O	System byte address
179	D[0]	1	Low	I/O	Data I/O
180	VSSCORE			Core ground	Core ground
181	VDDCORE			Core Pwr	Core power, 2.5 V
182	VSSIO			Pad ground	I/O ground
183	VDDIO			Pad Power	Digital I/O power, 3.3 V
184	CL[2]	1	Low	O	LCD pixel clock out
185	CL[1]	1	Low	O	LCD line clock
186	FRM	1	Low	O	LCD frame synchronization pulse
187	M	1	Low	O	LCD AC bias drive
188	DD[3]	1	Low	I/O	LCD serial display data
189	DD[2]	1	Low	I/O	LCD serial display data
190	VSSIO			Pad Gnd	I/O ground
191	DD[1]	1	Low	I/O	LCD serial display data
192	DD[0]	1	Low	I/O	LCD serial display data
193	nSDCS[1]	1	High	O	SDRAM chip select 1
194	nSDCS[0]	1	High	O	SDRAM chip select 0
195	SDQM[3]	2	Low	I/O	SDRAM byte lane mask
196	SDQM[2]	2	Low	I/O	SDRAM byte lane mask
197	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
198	VSSIO			Pad Gnd	I/O ground
199	SDCKE	2	Low	I/O	SDRAM clock enable output
200	SDCLK	2	Low	I/O	SDRAM clock out
201	nMWE/nSDWE	1	High	O	ROM, expansion write enable/ SDRAM write enable control signal
202	nMOE/nSDCAS	1	High	O	ROM, expansion OP enable/SDRAM CAS control signal
203	VSSIO			Pad Gnd	I/O ground
204	nCS[0]	1	High	O	Chip select 0
205	nCS[1]	1	High	O	Chip select 1

Table 20. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Strength †	Reset State	Type	Description
206	nCS[2]	1	High	O	Chip select 2
207	nCS[3]	1	High	O	Chip select 3
208	nCS[4]	1	High	O	Chip select 4

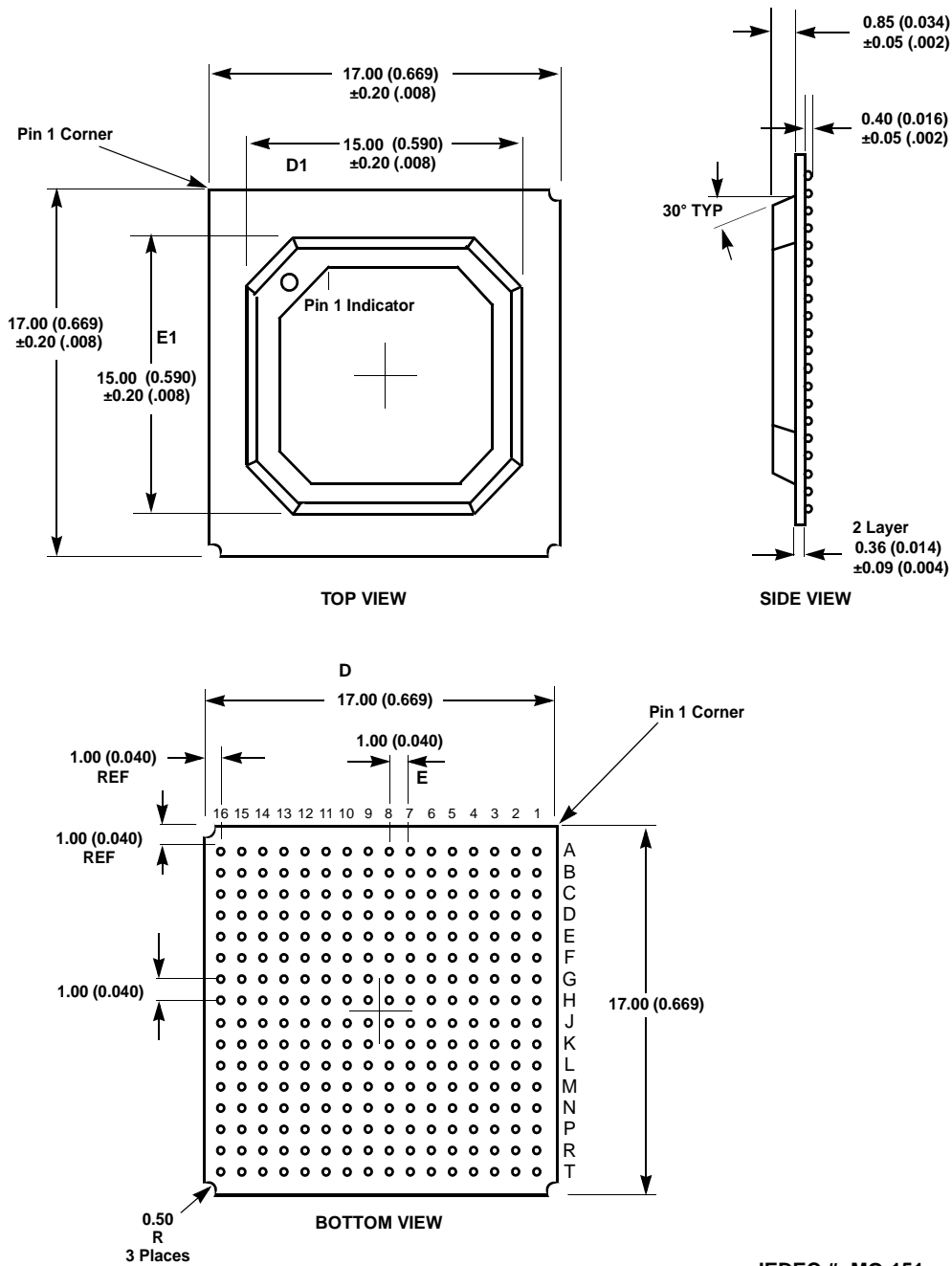
\*“With p/u” means with internal pull-up of 100 KOhms on the pin.

† Strength 1 = 4 ma

Strength 2 = 12 ma

‡ Input. Port A,B,D,E GPIOs default to input at nPOR and URESET conditions.

## 256-Ball PBGA Package Characteristics



JEDEC #: MO-151  
Ball Diameter: 0.50 mm ± 0.10 mm  
17 ¥ 17 ¥ 1.61 mm body

Figure 17. 256-Ball PBGA Package

- Note:
- 1) For pin locations see [Table 21](#).
  - 2) Dimensions are in millimeters (inches), and controlling dimension is millimeter
  - 3) Before beginning any new EP7312 design, contact Cirrus Logic for the latest package information.

**256-Ball PBGA Pinout (Top View)**

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
A	VDDIO	nCS[4]	nCS[1]	SDCLK	SDQM[3]	DD[1]	M	VDDIO	D[0]	D[2]	A[3]	VDDIO	A[6]	MOSCOUT	VDDOSC	VSSIO	A
B	nCS[5]	VDDIO	nCS[3]	nMOE/ nSDCAS	VDDIO	nSDCS[1]	DD[2]	CL[1]	VDDCORE	D[1]	A[2]	A[4]	A[5]	WAKEUP	VDDIO	nURESET	B
C	VDDIO	EXPCLK	VSSIO	VDDIO	VSSIO	VSSIO	VSSIO	VDDIO	VSSIO	VSSIO	VSSIO	VDDIO	VSSIO	VSSIO	nPOR	nEXTPWR	C
D	WRITE/ nSDRAS	EXPRDY	VSSIO	VDDIO	nCS[2]	nMWE/ nSDWE	nSDCS[0]	CL[2]	VSSRTC	D[4]	nPWRFL	MOSCIN	VDDIO	VSSIO	D[7]	D[8]	D
E	RXD[2]	PB[7]	TDI	WORD	VSSIO	nCS[0]	SDQM[2]	FRM	A[0]	D[5]	VSSOSC	VSSIO	nMEDCHG/ nBROM	VDDIO	D[9]	D[10]	E
F	PB[5]	PB[3]	VSSIO	TXD[2]	RUN/ CLKEN	VSSIO	SDCKE	DD[3]	A[1]	D[6]	VSSRTC	BATOK	nBATCHG	VSSIO	D[11]	VDDIO	F
G	PB[1]	VDDIO	TDO	PB[4]	PB[6]	VSSCore	VSSRTC	DD[0]	D[3]	VSSRTC	A[7]	A[8]	A[9]	VSSIO	D[12]	D[13]	G
H	PA[7]	PA[5]	VSSIO	PA[4]	PA[6]	PB[0]	PB[2]	VSSRTC	VSSRTC	A[10]	A[11]	A[12]	A[13]/ DRA[14]	VSSIO	D[14]	D[15]	H
J	PA[3]	PA[1]	VSSIO	PA[2]	PA[0]	TXD[1]	CTS	VSSRTC	VSSRTC	A[17]/ DRA[10]	A[16]/ DRA[11]	A[15]/ DRA[12]	A[14]/ DRA[13]	nTRST	D[16]	D[17]	J
K	LEDDRV	PHDIN	VSSIO	DCD	nTEST[1]	EINT[3]	VSSRTC	ADCIN	COL[4]	TCLK	D[20]	D[19]	D[18]	VSSIO	VDDIO	VDDIO	K
L	RXD[1]	DSR	VDDIO	nEINT[1]	PE[2]/ CLKSEL	VSSRTC	PD[0]/ LEDFLSH	VSSRTC	COL[6]	D[31]	VSSRTC	A[22]/ DRA[5]	A[21]/ DRA[6]	VSSIO	A[18]/ DRA[9]	A[19]/ DRA[8]	L
M	nTEST[0]	nEINT[2]	VDDIO	PE[0]/ BOOTSEL[0]	TMS	VDDIO	SSITXFR	DRIVE[1]	FB[0]	COL[0]	D[27]	VSSIO	A[23]/ DRA[4]	VDDIO	A[20]/ DRA[7]	D[21]	M
N	nEXTFIQ	PE[1]/ BOOTSEL[1]	VSSIO	VDDIO	PD[5]	PD[2]	SSIRXDA	ADCCLK	SMPCLK	COL[2]	D[29]	D[26]	HALFWORD	VSSIO	D[22]	D[23]	N
P	VSSRTC	RTCOUT	VSSIO	VSSIO	VDDIO	VSSIO	VSSIO	VDDIO	VSSIO	VDDIO	VSSIO	VSSIO	VDDIO	VSSIO	D[24]	VDDIO	P
R	RTCIN	VDDIO	PD[4]	PD[1]	SSITXDA	nADCCS	VDDIO	ADCOUT	COL[7]	COL[3]	COL[1]	D[30]	A[27]/ DRA[0]	A[25]/ DRA[2]	VDDIO	A[24]/ DRA[3]	R
T	VDDRTC	PD[7]/ SDQM[1]	PD[6]/ SDQM[0]	PD[3]	SSICLK	SSIRXFR	VDDCORE	DRIVE[0]	FB[1]	COL[5]	VDDIO	BUZ	D[28]	A[26]/ DRA[1]	D[25]	VSSIO	T

## 256-Ball PBGA Ball Listing

The list is ordered by ball location.

Table 21. 256-Ball PBGA Ball Listing

Ball Location	Name	Strength †	Reset State	Type	Description
A1	VDDIO			Pad power	Digital I/O power, 3.3 V
A2	nCS[4]	1	High	O	Chip select 4
A3	nCS[1]	1	High	O	Chip select 1
A4	SDCLK	2	Low	O	SDRAM clock out
A5	SDQM[3]	2	Low	O	SDRAM byte lane mask
A6	DD[1]	1	Low	O	LCD serial display data
A7	M	1	Low	O	LCD AC bias drive
A8	VDDIO			Pad power	Digital I/O power, 3.3 V
A9	D[0]	1	Low	I/O	Data I/O
A10	D[2]	1	Low	I/O	Data I/O
A11	A[3]	2	Low	O	System byte address
A12	VDDIO			Pad power	Digital I/O power, 3.3V
A13	A[6]	1	Low	O	System byte address
A14	MOSCOU			O	Main oscillator out
A15	VDDOSC			Oscillator power	Oscillator power in, 2.5 V
A16	VSSIO			Pad ground	I/O ground
B1	nCS[5]	1	Low	O	Chip select 5
B2	VDDIO			Pad power	Digital I/O power, 3.3 V
B3	nCS[3]	1	High	O	Chip select 3
B4	nMOE/nSDCAS	1	High	O	ROM, expansion OP enable/SDRAM CAS control signal
B5	VDDIO			Pad power	Digital I/O power, 3.3 V
B6	nSDCS[1]	1	High	O	SDRAM chip select 1
B7	DD[2]	1	Low	O	LCD serial display data
B8	CL[1]	1	Low	O	LCD line clock
B9	VDDCORE			Core power	Digital core power, 2.5V
B10	D[1]	1	Low	I/O	Data I/O
B11	A[2]	2	Low	O	System byte address
B12	A[4]	1	Low	O	System byte address
B13	A[5]	1	Low	O	System byte address
B14	WAKEUP	Schmitt		I	System wake up input
B15	VDDIO			Pad power	Digital I/O power, 3.3 V
B16	nURESET	Schmitt		I	User reset input
C1	VDDIO			Pad power	Digital I/O power, 3.3V
C2	EXPCLK	1		I	Expansion clock input
C3	VSSIO			Pad ground	I/O ground
C4	VDDIO			Pad power	Digital I/O power, 3.3 V
C5	VSSIO			Pad ground	I/O ground
C6	VSSIO			Pad ground	I/O ground
C7	VSSIO			Pad ground	I/O ground
C8	VDDIO			Pad power	Digital I/O power, 3.3 V
C9	VSSIO			Pad ground	I/O ground
C10	VSSIO			Pad ground	I/O ground
C11	VSSIO			Pad ground	I/O ground
C12	VDDIO			Pad power	Digital I/O power, 3.3 V
C13	VSSIO			Pad ground	I/O ground



**Table 21. 256-Ball PBGA Ball Listing (Continued)**

Ball Location	Name	Strength †	Reset State	Type	Description
C14	VSSIO			Pad ground	I/O ground
C15	nPOR	Schmitt		I	Power-on reset input
C16	nEXTPWR			I	External power supply sense input
D1	WRITE/nSDRAS	1	Low	O	Transfer direction / SDRAM RAS signal output
D2	EXPRDY	1		I	Expansion port ready input
D3	VSSIO			Pad ground	I/O ground
D4	VDDIO			Pad power	Digital I/O power, 3.3V
D5	nCS[2]	1	High	O	Chip select 2
D6	nMWE/nSDWE	1	High	O	ROM, expansion write enable/ SDRAM write enable control signal
D7	nSDCS[0]	1	High	O	SDRAM chip select 2
D8	CL[2]	1	Low	O	LCD pixel clock out
D9	VSSRTC			Core ground	Real time clock ground
D10	D[4]	1	Low	I/O	Data I/O
D11	nPWRFL			I	Power fail sense input
D12	MOSCIN			I	Main oscillator input
D13	VDDIO			Pad power	Digital I/O power, 3.3V
D14	VSSIO			Pad ground	I/O ground
D15	D[7]	1	Low	I/O	Data I/O
D16	D[8]	1	Low	I/O	Data I/O
E1	RXD[2]			I	UART 2 receive data input
E2	PB[7]	1	Input †	I	GPIO port B
E3	TDI	with p/u*		I	JTAG data input
E4	WORD	1	Low	O	Word access select output
E5	VSSIO			Pad ground	I/O ground
E6	nCS[0]	1	High	O	Chip select 0
E7	SDQM[2]	2	Low	O	SDRAM byte lane mask
E8	FRM	1	Low	O	LCD frame synchronization pulse
E9	A[0]	2	Low	O	System byte address
E10	D[5]	1	Low	I/O	Data I/O
E11	VSSOSC			Oscillator ground	PLL ground
E12	VSSIO			Pad ground	I/O ground
E13	nMEDCHG/nBROM			I	Media change interrupt input / internal ROM boot enable
E14	VDDIO			Pad power	Digital I/O power, 3.3V
E15	D[9]	1	Low	I/O	Data I/O
E16	D[10]	1	Low	I/O	Data I/O
F1	PB[5]	1	Input †	I	GPIO port B
F2	PB[3]	1	Input †	I	GPIO port B
F3	VSSIO			Pad ground	I/O ground
F4	TXD[2]	1	High	O	UART 2 transmit data output
F5	RUN/CLKEN	1	Low	O	Run output / clock enable output
F6	VSSIO			Pad ground	I/O ground
F7	SDCKE	2	Low	O	SDRAM clock enable output
F8	DD[3]	1	Low	O	LCD serial display data
F9	A[1]	2	Low	O	System byte address
F10	D[6]	1	Low	I/O	Data I/O
F11	VSSRTC			RTC ground	Real time clock ground
F12	BATOK			I	Battery OK input

Table 21. 256-Ball PBGA Ball Listing (Continued)

Ball Location	Name	Strength †	Reset State	Type	Description
F13	nBATCHG			I	Battery changed sense input
F14	VSSIO			Pad ground	I/O ground
F15	D[11]	1	Low	I/O	Data I/O
F16	VDDIO			Pad power	Digital I/O power, 3.3V
G1	PB[1]	1	Input †	I	GPIO port B
G2	VDDIO			Pad power	Digital I/O power, 3.3V
G3	TDO	1	Input †	O	JTAG data out
G4	PB[4]	1	Input †	I	GPIO port B
G5	PB[6]	1	Input †	I	GPIO port B
G6	VSSCore			Core ground	Core ground
G7	VSSRTC			RTC ground	Real time clock ground
G8	DD[0]	1	Low	O	LCD serial display data
G9	D[3]	1	Low	I/O	Data I/O
G10	VSSRTC			RTC ground	Real time clock ground
G11	A[7]	1	Low	O	System byte address
G12	A[8]	1	Low	O	System byte address
G13	A[9]	1	Low	O	System byte address
G14	VSSIO			Pad ground	I/O ground
G15	D[12]	1	Low	I/O	Data I/O
G16	D[13]	1	Low	I/O	Data I/O
H1	PA[7]	1	Input †	I/O	GPIO port A
H2	PA[5]	1	Input †	I/O	GPIO port A
H3	VSSIO			Pad ground	I/O ground
H4	PA[4]	1	Input †	I/O	GPIO port A
H5	PA[6]	1	Input †	I/O	GPIO port A
H6	PB[0]	1	Input †	I/O	GPIO port B
H7	PB[2]	1	Input †	I/O	GPIO port B
H8	VSSRTC			RTC ground	Real time clock ground
H9	VSSRTC			RTC ground	Real time clock ground
H10	A[10]	1	Low	O	System byte address
H11	A[11]	1	Low	O	System byte address
H12	A[12]	1	Low	O	System byte address
H13	A[13]/DRA[14]	1	Low	O	System byte address / SDRAM address
H14	VSSIO			Pad ground	I/O ground
H15	D[14]	1	Low	I/O	Data I/O
H16	D[15]	1	Low	I/O	Data I/O
J1	PA[3]	1	Input †	I/O	GPIO port A
J2	PA[1]	1	Input †	I/O	GPIO port A
J3	VSSIO			Pad ground	I/O ground
J4	PA[2]	1	Input †	I/O	GPIO port A
J5	PA[0]	1	Input †	I/O	GPIO port A
J6	TXD[1]	1	High	O	UART 1 transmit data out

**Table 21. 256-Ball PBGA Ball Listing (Continued)**

Ball Location	Name	Strength †	Reset State	Type	Description
J7	CTS			I	UART 1 clear to send input
J8	VSSRTC			RTC ground	Real time clock ground
J9	VSSRTC			RTC ground	Real time clock ground
J10	A[17]/DRA[10]	1	Low	O	System byte address / SDRAM address
J11	A[16]/DRA[11]	1	Low	O	System byte address / SDRAM address
J12	A[15]/DRA[12]	1	Low	O	System byte address / SDRAM address
J13	A[14]/DRA[13]	1	Low	O	System byte address / SDRAM address
J14	nTRST			I	JTAG async reset input
J15	D[16]	1	Low	I/O	Data I/O
J16	D[17]	1	Low	I/O	Data I/O
K1	LEDDRV	1	Low	O	IR LED drive
K2	PHDIN			I	Photodiode input
K3	VSSIO			Pad ground	I/O ground
K4	DCD			I	UART 1 data carrier detect
K5	nTEST[1]	With p/u*		I	Test mode select input
K6	EINT[3]			I	External interrupt
K7	VSSRTC			RTC ground	Real time clock ground
K8	ADCIN			I	SSI1 ADC serial input
K9	COL[4]	1	High	O	Keyboard scanner column drive
K10	TCLK			I	JTAG clock
K11	D[20]	1	Low	I/O	Data I/O
K12	D[19]	1	Low	I/O	Data I/O
K13	D[18]	1	Low	I/O	Data I/O
K14	VSSIO			Pad ground	I/O ground
K15	VDDIO			Pad power	Digital I/O power, 3.3V
K16	VDDIO			Pad power	Digital I/O power, 3.3V
L1	RXD[1]			I	UART 1 receive data input
L2	DSR			I	UART 1 data set ready input
L3	VDDIO			Pad power	Digital I/O power, 3.3V
L4	nEINT[1]			I	External interrupt input
L5	PE[2]/CLKSEL	1	Input †	I/O	GPIO port E / clock input mode select
L6	VSSRTC			RTC ground	Real time clock ground
L7	PD[0]/LEDFLSH	1	Low	I/O	GPIO port D / LED blinker output
L8	VSSRTC			Core ground	Real time clock ground
L9	COL[6]	1	High	O	Keyboard scanner column drive
L10	D[31]	1	Low	I/O	Data I/O
L11	VSSRTC			RTC ground	Real time clock ground
L12	A[22]/DRA[5]	1	Low	O	System byte address / SDRAM address
L13	A[21]/DRA[6]	1	Low	O	System byte address / SDRAM address
L14	VSSIO			Pad ground	I/O ground
L15	A[18]/DRA[9]	1	Low	O	System byte address / SDRAM address
L16	A[19]/DRA[8]	1	Low	O	System byte address / SDRAM address
M1	nTEST[0]	With p/u*		I	Test mode select input
M2	nEINT[2]			I	External interrupt input
M3	VDDIO			Pad power	Digital I/O power, 3.3V
M4	PE[0]/BOOTSEL[0]	1	Input †	I	GPIO port E / Boot mode select
M5	TMS	with p/u*		I	JTAG mode select

Table 21. 256-Ball PBGA Ball Listing (Continued)

Ball Location	Name	Strength †	Reset State	Type	Description
M6	VDDIO			Pad power	Digital I/O power, 3.3V
M7	SSITXFR	1	Low	I/O	DAI/CODEC/SSI2 frame sync
M8	DRIVE[1]	2	High / Low	I/O	PWM drive output
M9	FB[0]			I	PWM feedback input
M10	COL[0]	1	High	O	Keyboard scanner column drive
M11	D[27]	1	Low	I/O	Data I/O
M12	VSSIO			Pad ground	I/O ground
M13	A[23]/DRA[4]	1	Low	O	System byte address / SDRAM address
M14	VDDIO			Pad power	Digital I/O power, 3.3V
M15	A[20]/DRA[7]	1	Low	O	System byte address / SDRAM address
M16	D[21]	1	Low	I/O	Data I/O
N1	nEXTFIQ			I	External fast interrupt input
N2	PE[1]/BOOTSEL[1]	1	Input ‡	I/O	GPIO port E / boot mode select
N3	VSSIO			Pad ground	I/O ground
N4	VDDIO			Pad power	Digital I/O power, 3.3V
N5	PD[5]	1	Low	I/O	GPIO port D
N6	PD[2]	1	Low	I/O	GPIO port D
N7	SSIRXDA			I/O	DAI/CODEC/SSI2 serial data input
N8	ADCCLK	1	Low	O	SSI1 ADC serial clock
N9	SMPCLK	1	Low	O	SSI1 ADC sample clock
N10	COL[2]	1	High	O	Keyboard scanner column drive
N11	D[29]	1	Low	I/O	Data I/O
N12	D[26]	1	Low	I/O	Data I/O
N13	HALFWORD	1	Low	O	Halfword access select output
N14	VSSIO			Pad ground	I/O ground
N15	D[22]	1	Low	I/O	Data I/O
N16	D[23]	1	Low	I/O	Data I/O
P1	VSSRTC			RTC ground	Real time clock ground
P2	RTCOUT			O	Real time clock oscillator output
P3	VSSIO			Pad ground	I/O ground
P4	VSSIO			Pad ground	I/O ground
P5	VDDIO			Pad power	Digital I/O power, 3.3V
P6	VSSIO			Pad ground	I/O ground
P7	VSSIO			Pad ground	I/O ground
P8	VDDIO			Pad power	Digital I/O power, 3.3V
P9	VSSIO			Pad ground	I/O ground
P10	VDDIO			Pad power	Digital I/O power, 3.3V
P11	VSSIO			Pad ground	I/O ground
P12	VSSIO			Pad ground	I/O ground
P13	VDDIO			Pad power	Digital I/O power
P14	VSSIO			Pad ground	I/O ground
P15	D[24]	1	Low	I/O	Data I/O
P16	VDDIO			Pad power	Digital I/O power, 3.3V
R1	RTCIN			I/O	Real time clock oscillator input
R2	VDDIO			Pad power	Digital I/O power, 3.3V
R3	PD[4]	1	Low	I/O	GPIO port D
R4	PD[1]	1	Low	I/O	GPIO port D

**Table 21. 256-Ball PBGA Ball Listing (Continued)**

Ball Location	Name	Strength †	Reset State	Type	Description
R5	SSITXDA	1	Low	O	DAI/CODEC/SSI2 serial data output
R6	nADCCS	1	High	O	SSI1 ADC chip select
R7	VDDIO			Pad power	Digital I/O power, 3.3V
R8	ADCOUT	1	Low	O	SSI1 ADC serial data output
R9	COL[7]	1	High	O	Keyboard scanner column drive
R10	COL[3]	1	High	O	Keyboard scanner column drive
R11	COL[1]	1	High	O	Keyboard scanner column drive
R12	D[30]	1	Low	I/O	Data I/O
R13	A[27]/DRA[0]	2	Low	O	System byte address / SDRAM address
R14	A[25]/DRA[2]	2	Low	O	System byte address / SDRAM address
R15	VDDIO			Pad power	Digital I/O power, 3.3V
R16	A[24]/DRA[3]	1	Low	O	System byte address / SDRAM address
T1	VDDRTC			RTC power	Real time clock power, 2.5V
T2	PD[7]/SDQM[1]	1	Low	I/O	GPIO port D / SDRAM byte lane mask
T3	PD[6]/SDQM[0]	1	Low	I/O	GPIO port D / SDRAM byte lane mask
T4	PD[3]	1	Low	I/O	GPIO port D
T5	SSICLK	1	Input ‡	I/O	DAI/CODEC/SSI2 serial clock
T6	SSIRXFR	1	Input ‡	I/O	DAI/CODEC/SSI2 frame sync
T7	VDDCORE			Core power	Core power, 2.5V
T8	DRIVE[0]	2	High / Low	I/O	PWM drive output
T9	FB[1]			I	PWM feedback input
T10	COL[5]	1	High	O	Keyboard scanner column drive
T11	VDDIO			Pad power	Digital I/O power, 3.3V
T12	BUZ	1	Low	O	Buzzer drive output
T13	D[28]	1	Low	I/O	Data I/O
T14	A[26]/DRA[1]	2	Low	O	System byte address / SDRAM address
T15	D[25]	1	Low	I/O	Data I/O
T16	VSSIO			Pad ground	I/O ground

\* "With p/u" means with internal pull-up of 100 KOhms on the pin.

† Strength 1 = 4 ma  
 Strength 2 = 12 ma

‡ Input. Port A,B,D,E GPIOs default to input at nPOR and URESET conditions.

## JTAG Boundary Scan Signal Ordering

**Table 22. JTAG Boundary Scan Signal Ordering**

LQFP Pin No.	PBGA Ball	Signal	Type	Position
1	B1	nCS[5]	O	1
4	C2	EXPCLK	I/O	3
5	E4	WORD	O	6
6	D1	WRITE/nSDRAS	O	8
7	F5	RUN/CLKEN	O	10
8	D2	EXPRDY	I	13

Table 22. JTAG Boundary Scan Signal Ordering (Continued)

LQFP Pin No.	PBGA Ball	Signal	Type	Position
9	F4	TXD2	O	14
10	E1	RXD2	I	16
13	E2	PB[7]	I/O	17
14	G5	PB[6]	I/O	20
15	F1	PB[5]	I/O	23
16	G4	PB[4]	I/O	26
17	F2	PB[3]	I/O	29
18	H7	PB[2]	I/O	32
19	G1	PB[1]	I/O	35
20	H6	PB[0]	I/O	38
23	H1	PA[7]	I/O	41
24	H5	PA[6]	I/O	44
25	H2	PA[5]	I/O	47
26	H4	PA[4]	I/O	50
27	J1	PA[3]	I/O	53
28	J4	PA[2]	I/O	56
29	J2	PA[1]	I/O	59
30	J5	PA[0]	I/O	62
31	K1	LEDDRV	O	65
32	J6	TXD1	O	67
34	K2	PHDIN	I	69
35	J7	CTS	I	70
36	L1	RXD1	I	71
37	K4	DCD	I	72
38	L2	DSR	I	73
39	K5	nTEST1	I	74
40	M1	nTEST0	I	75
41	K6	EINT3	I	76
42	M2	nEINT2	I	77
43	L4	nEINT1	I	78
44	N1	nEXTFIQ	I	79
45	L5	PE[2]/CLKSEL	I/O	80
46	N2	PE[1]/ BOOTSEL[1]	I/O	83
47	M4	PE[0]/BOOTSEL0	I/O	86
53	T2	PD[7]/SDQM[1]	I/O	89
54	T3	PD[6]/SDQM[0]	I/O	92
55	N5	PD[5]	I/O	95
56	R3	PD[4]	I/O	98
59	T4	PD[3]	I/O	101
60	N6	PD[2]	I/O	104

**Table 22. JTAG Boundary Scan Signal Ordering (Continued)**

<b>LQFP Pin No.</b>	<b>PBGA Ball</b>	<b>Signal</b>	<b>Type</b>	<b>Position</b>
61	R4	PD[1]	I/O	107
62	L7	PD[0]/LEDFLSH	O	110
68	T6	SSIRXFR	I/O	122
69	K8	ADCIN	I	125
70	R6	nADCCS	O	126
75	M8	DRIVE1	I/O	128
76	T8	DRIVE0	I/O	131
77	N8	ADCCLK	O	134
78	R8	ADCOUT	O	136
79	N9	SMPCLK	O	138
80	T9	FB1	I	140
82	M9	FB0	I	141
83	R9	COL7	O	142
84	L9	COL6	O	144
85	T10	COL5	O	146
86	K9	COL4	O	148
87	R10	COL3	O	150
88	N10	COL2	O	152
91	R11	COL1	O	154
92	M10	COL0	O	156
93	T12	BUZ	O	158
94	L10	D[31]	I/O	160
95	R12	D[30]	I/O	163
96	N11	D[29]	I/O	166
97	T13	D[28]	I/O	169
99	R13	A[27]/DRA[0]	Out	172
100	M11	D[27]	I/O	174
101	T14	A[26]/DRA[1]	O	177
102	N12	D[26]	I/O	179
103	R14	A[25]/DRA[2]	O	182
104	T15	D[25]	I/O	184
105	N13	HALFWORD	O	187
106	R16	A[24]/DRA[3]	O	189
109	P15	D[24]	I/O	191
110	M13	A[23]/DRA[4]	O	194
111	N16	D[23]	I/O	196
112	L12	A[22]/DRA[5]	O	199
113	N15	D[22]	I/O	201
114	L13	A[21]/DRA[6]	O	204
115	M16	D[21]	I/O	206
117	M15	A[20]/DRA[7]	O	209

Table 22. JTAG Boundary Scan Signal Ordering (Continued)

LQFP Pin No.	PBGA Ball	Signal	Type	Position
118	K11	D[20]	I/O	211
119	L16	A[19]/DRA[8]	O	214
120	K12	D[19]	I/O	216
121	L15	A[18]/DRA[9]	O	219
122	K13	D[18]	I/O	221
126	J10	A[17]/DRA[10]	O	224
127	J16	D[17]	I/O	226
128	J11	A[16]/DRA[11]	O	229
129	J15	D[16]	I/O	231
130	J12	A[15]/DRA[12]	O	234
131	H16	D[15]	I/O	236
132	J13	A[14]/DRA[13]	O	239
133	H15	D[14]	I/O	241
134	H13	A[13]/DRA[14]	O	244
135	G16	D[13]	I/O	246
136	H12	A[12]	O	249
137	G15	D[12]	I/O	251
138	H11	A[11]	O	254
141	F15	D[11]	I/O	256
142	H10	A[10]	O	259
143	E16	D[10]	I/O	261
144	G13	A[9]	O	264
145	E15	D[9]	I/O	266
146	G12	A[8]	O	269
147	D16	D[8]	I/O	271
148	G11	A[7]	O	274
150	D15	D[7]	I/O	276
151	F13	nBATCHG	I	279
152	C16	nEXTPWR	I	280
153	F12	BATOK	I	281
154	C15	nPOR	I	282
155	E13	nMEDCHG/nBROM	I	283
156	B16	nURESET	I	284
161	B14	WAKEUP	I	285
162	D11	nPWRFL	I	286
163	A13	A[6]	O	287
164	F10	D[6]	I/O	289
165	B13	A[5]	O	292
166	E10	D[5]	I/O	294
169	B12	A[4]	O	297
170	D10	D[4]	I/O	299



**Table 22. JTAG Boundary Scan Signal Ordering (Continued)**

<b>LQFP Pin No.</b>	<b>PBGA Ball</b>	<b>Signal</b>	<b>Type</b>	<b>Position</b>
171	A11	A[3]	O	302
172	G9	D[3]	I/O	304
173	B11	A[2]	O	307
175	A10	D[2]	I/O	309
176	F9	A[1]	O	312
177	B10	D[1]	I/O	314
178	E9	A[0]	O	317
179	A9	D[0]	I/O	319
184	D8	CL2	O	322
185	B8	CL1	O	324
186	E8	FRM	O	326
187	A7	M	O	328
188	F8	DD[3]	O	330
189	B7	DD[2]	O	333
191	A6	DD[1]	O	336
192	G8	DD[0]	O	339
193	B6	nSDCS[1]	O	342
194	D7	nSDCS[0]	O	344
195	A5	SDQM[3]	I/O	346
196	E7	SDQM[2]	I/O	349
199	F7	SDCKE	I/O	352
200	A4	SDCLK	I/O	355
201	D6	nMWE/nSDWE	O	358
202	B4	nMOE/nSDCAS	O	360
204	E6	nCS[0]	O	362
205	A3	nCS[1]	O	364
206	D5	nCS[2]	O	366
207	B3	nCS[3]	O	368
208	A2	nCS[4]	O	370

1) See EP7312 Users' Manual for pin naming / functionality.

2) For each pad, the JTAG connection ordering is input, output, then enable as applicable.

## CONVENTIONS

This section presents acronyms, abbreviations, units of measurement, and conventions used in this data sheet.

### Acronyms and Abbreviations

Table 23 lists abbreviations and acronyms used in this data sheet.

Table 23. Acronyms and Abbreviations

Acronym/ Abbreviation	Definition
A/D	analog-to-digital
ADC	analog-to-digital converter
CODEC	coder / decoder
D/A	digital-to-analog
DMA	direct-memory access
EPB	embedded peripheral bus
FCS	frame check sequence
FIFO	first in / first out
FIQ	fast interrupt request
GPIO	general purpose I/O
ICT	in circuit test
IR	infrared
IRQ	standard interrupt request
IrDA	Infrared Data Association
JTAG	Joint Test Action Group
LCD	liquid crystal display
LED	light-emitting diode
LQFP	low profile quad flat pack
LSB	least significant bit
MIPS	millions of instructions per second
MMU	memory management unit
MSB	most significant bit
PBGA	plastic ball grid array
PCB	printed circuit board
PDA	personal digital assistant
PLL	phase locked loop
p/u	pull-up resistor
RISC	reduced instruction set computer
RTC	Real-Time Clock
SIR	slow (9600–115.2 kbps) infrared
SRAM	static random access memory
SSI	synchronous serial interface

Table 23. Acronyms and Abbreviations (Continued)

Acronym/ Abbreviation	Definition
TAP	test access port
TLB	translation lookaside buffer
UART	universal asynchronous receiver

### Units of Measurement

Table 24. Unit of Measurement

Symbol	Unit of Measure
°C	degree Celsius
fs	sample frequency
Hz	hertz (cycle per second)
kbps	kilobits per second
KB	kilobyte (1,024 bytes)
kHz	kilohertz
kΩ	kilo Ohm
Mbps	megabits (1,048,576 bits) per second
MB	megabyte (1,048,576 bytes)
MBps	megabytes per second
MHz	megahertz (1,000 kilohertz)
μA	microampere
μF	microfarad
μW	microwatt
μs	microsecond (1,000 nanoseconds)
mA	milliampere
mW	milliwatt
ms	millisecond (1,000 microseconds)
ns	nanosecond
V	volt
W	watt

## General Conventions

Hexadecimal numbers are presented with all letters in uppercase and a lowercase “h” appended or with a 0x at the beginning. For example, 0x14 and 03CAh are hexadecimal numbers. Binary numbers are enclosed in single quotation marks when in text (for example, ‘11’ designates a binary number). Numbers not indicated by an “h”, 0x or quotation marks are decimal.

Registers are referred to by acronym, with bits listed in brackets separated by a colon (:) (for example, CODR[7:0]), and are described in the *EP7312 User’s Manual*. The use of “TBD” indicates values that are “to be determined,” “n/a” designates “not available,” and “n/c” indicates a pin that is a “no connect.”

## Pin Description Conventions

Abbreviations used for signal directions are listed in [Table 25](#).

**Table 25. Pin Description Conventions**

Abbreviation	Direction
I	Input
O	Output
I/O	Input or Output

## Ordering Information

Model	Temperature	Package
EP7312-CBZ	0 to +70 °C	256-pin PBGA, 17mm X 17mm
EP7312-IBZ	-40 to +85 °C.	
EP7312-CVZ	0 to +70 °C	208-pin LQFP.
EP7312-CV-90Z (90 MHz)		
EP7312-IVZ	-40 to +85 °C.	

## Environmental, Manufacturing, & Handling Information

Model Number	Peak Reflow Temp	MSL Rating*	Max Floor Life
EP7312-CBZ	260 °C	3	7 Days
EP7312-CVZ			
EP7312-CV-90Z (90 MHz)			
EP7312-IBZ			
EP7312-IVZ			

\* MSL (Moisture Sensitivity Level) as specified by IPC/JEDEC J-STD-020.

All devices are now lead (Pb) free.

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## Revision History

Revision	Date	Changes
PP5	JAN 2004	Preliminary release. Updated SDRAM timing.
F1	AUG 2005	Updated ordering information. Added MSL data.
F2	MAR 2011	Removed all lead-containing device ordering information. Removed 204-pin TFBGA package option.

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## Contacting Cirrus Logic Support

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